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## Ultra-Low Quiescent Current Buck

### General Description

DA9230 is an ultra-low quiescent current, high efficiency buck regulator in a compact I<sup>2</sup>C configurable WLCSP package targeting battery powered applications needing highly efficient power supplies.

The battery life of these devices is significantly improved due to the low quiescent current delivered by DA9230 during operation and shutdown.

The buck regulator extends high light load efficiency down to 10 uA further extending battery life. Dynamic Voltage Control in the Buck regulator facilitates optimization across the system power modes enabling further improvement in System efficiency and battery life.

DA9230 provides multiple protection features and comes with the ability to monitor the events and indicators in the GPO pin.

Suitable for space constrained applications, the DA9230 comes in a 1.65 mm x 1.25 mm, 12-pin WLCSP package.

### Key Features

- 300 mA buck regulator
  - 750 nA total input current (buck enabled no load)
  - Up to 81% efficiency at 1.8 V output, 10 μA load currents
  - Input voltage 2.5 V to 5.5 V (Minimum 2.75 V for start up)
  - Output voltage 0.6 V to 1.9 V
  - Dynamic Voltage Control (DVC)
- I<sup>2</sup>C interface for device configuration and control
- Protection features and System Monitors
- Small 1.65 mm x 1.25 mm, 12-pin WLCSP package

### Applications

- Wearables – wrist wear, hearables
- Smart devices - thermostats and door locks
- Smoke detectors
- Portable medical devices
- Remote sensors
- High efficiency, low power applications

## Ultra-Low Quiescent Current Buck

### Contents

General Description .....	1
Key Features .....	1
Applications .....	1
Contents .....	1
Figures.....	3
Tables .....	4
<b>1 Terms and Definitions.....</b>	<b>6</b>
<b>2 Block and Application Diagrams .....</b>	<b>7</b>
<b>3 Pinout .....</b>	<b>8</b>
<b>4 Absolute Maximum Ratings .....</b>	<b>10</b>
<b>5 Recommended Operating Conditions.....</b>	<b>11</b>
<b>6 ESD Ratings .....</b>	<b>12</b>
<b>7 Electrical Characteristics .....</b>	<b>13</b>
<b>8 Thermal Characteristics .....</b>	<b>16</b>
<b>9 Typical Operating Characteristics.....</b>	<b>17</b>
9.1 Buck No Load Quiescent Current vs Temperature, Device is Switching.....	17
9.2 RDSon vs Temperature .....	17
9.3 Efficiency vs Load Current .....	18
9.4 Switching Frequency vs Load Current.....	19
9.5 Buck V <sub>OUT</sub> Ripple vs Load Current.....	20
9.6 Buck V <sub>OUT</sub> vs Load Current .....	21
9.7 Typical Mode Operation.....	22
9.8 Buck Load Transient Response.....	23
9.9 Buck Dynamic Voltage Control .....	25
9.10 Device Enable and Start up .....	26
<b>10 Feature Descriptions.....</b>	<b>27</b>
10.1 Chip Enable and Disable Through IC_EN .....	27
10.2 VDD Under-Voltage Lockout.....	27
10.3 Over-Temperature Protection .....	27
10.4 Buck Regulator.....	27
10.4.1 Buck Output Voltage Programability.....	27
10.4.2 Start-up Operation .....	28
10.4.3 Power Saving Mode Operation.....	28
10.4.4 Dynamic Voltage Control .....	29
10.4.5 Cycle-by-cycle Over-Current Protection .....	29
10.4.6 Output Over-Voltage Protection .....	29
10.4.7 Output Under-Voltage Protection .....	29
10.4.8 Automatic Output voltage Discharge .....	29
10.4.9 Event Flag and Fault Control.....	30

## Ultra-Low Quiescent Current Buck

10.5	I <sup>2</sup> C Programming.....	31
10.5.1	Interface Description.....	31
10.5.2	Details of the I <sup>2</sup> C Protocol.....	31
10.6	GPO Pin Function Programming .....	32
10.6.1	Power Good Indicator .....	32
10.6.2	Event Indicator .....	32
10.6.3	Reset Pulse Generation.....	32
10.6.4	Always Pull-Down or Hi-Z.....	32
<b>11</b>	<b>Register Overview .....</b>	<b>33</b>
11.1	Register Map.....	33
11.1.1	Buck Control .....	33
11.1.2	System Module .....	34
11.2	Register Definitions .....	34
11.2.1	Buck Control .....	34
11.2.1.1	Event/Status/Mask Registers .....	34
11.2.1.2	User Registers .....	36
11.2.2	System Module .....	41
11.2.2.1	System Reset Registers .....	41
11.2.2.2	System ID Registers .....	42
<b>12</b>	<b>Package Information .....</b>	<b>44</b>
12.1	Package Outlines .....	44
12.2	Moisture Sensitivity Level.....	45
12.3	Soldering Information .....	45
<b>13</b>	<b>Ordering Information .....</b>	<b>46</b>
	<b>Contacting Dialog Semiconductor .....</b>	<b>47</b>

## Figures

Figure 1:	Block Diagram .....	7
Figure 2:	DA9230 Application Diagram .....	7
Figure 3:	Pinout Diagram (Top View) .....	8
Figure 4:	Buck V <sub>OUT</sub> = 1.8 V .....	17
Figure 5:	Buck V <sub>OUT</sub> = 0.9 V .....	17
Figure 6:	High-Side FET .....	17
Figure 7:	Low-Side FET.....	17
Figure 8:	Buck V <sub>OUT</sub> = 1.9 V .....	18
Figure 9:	Buck V <sub>OUT</sub> = 1.8 V .....	18
Figure 10:	Buck V <sub>OUT</sub> = 1.2 V .....	18
Figure 11:	Buck V <sub>OUT</sub> = 0.9 V .....	18
Figure 12:	Buck V <sub>OUT</sub> = 0.6 V .....	18
Figure 13:	Buck V <sub>OUT</sub> = 1.9 V .....	19
Figure 14:	Buck V <sub>OUT</sub> = 0.9 V .....	19
Figure 15:	Buck V <sub>OUT</sub> = 1.2 V .....	19
Figure 16:	Buck V <sub>OUT</sub> = 0.6 V .....	19
Figure 17:	Buck V <sub>OUT</sub> = 1.9 V .....	20

## Ultra-Low Quiescent Current Buck

Figure 18: Buck $V_{OUT} = 1.3\text{ V}$ .....	20
Figure 19: Buck $V_{OUT} = 0.9\text{ V}$ .....	20
Figure 20: Buck $V_{OUT} = 0.6\text{ V}$ .....	20
Figure 21: Buck $V_{OUT} = 1.9\text{ V}$ .....	21
Figure 22: Buck $V_{OUT} = 1.2\text{ V}$ .....	21
Figure 23: Buck $V_{OUT} = 0.9\text{ V}$ .....	21
Figure 24: Buck $V_{OUT} = 0.6\text{ V}$ .....	21
Figure 25: Buck $V_{IN} = 3.6\text{ V}$ , Buck $V_{OUT} = 1.8\text{ V}$ , Buck $I_{LOAD} = 1\text{ mA}$ .....	22
Figure 26: Buck $V_{IN} = 3.6\text{ V}$ , Buck $V_{OUT} = 1.8\text{ V}$ , Buck $I_{LOAD} = 10\text{ mA}$ .....	22
Figure 27: Buck $V_{IN} = 3.6\text{ V}$ , Buck $V_{OUT} = 1.8\text{ V}$ , Buck $I_{LOAD} = 100\text{ mA}$ .....	22
Figure 28: Buck $V_{IN} = 3.6\text{ V}$ , Buck $V_{OUT} = 1.8\text{ V}$ , Buck $I_{LOAD} = 300\text{ mA}$ .....	22
Figure 29: Buck $I_{LOAD} = 10\text{ mA}$ to $300\text{ mA}$ to $10\text{ mA}$ ( $0.3\text{ A}/\mu\text{s}$ ); Buck $V_{IN} = 3.6\text{ V}$ , Buck $V_{OUT} = 1.8\text{ V}$ 23	
Figure 30: Buck $I_{LOAD} = 100\text{ mA}$ to $300\text{ mA}$ to $100\text{ mA}$ ( $0.2\text{ A}/\mu\text{s}$ ); Buck $V_{IN} = 3.6\text{ V}$ , Buck $V_{OUT} = 1.8\text{ V}$ .....	23
Figure 31: Buck $I_{LOAD} = 10\text{ mA}$ to $300\text{ mA}$ to $10\text{ mA}$ ( $0.3\text{ A}/\mu\text{s}$ ); Buck $V_{IN} = 3.6\text{ V}$ , Buck $V_{OUT} = 1.2\text{ V}$ 23	
Figure 32: Buck $I_{LOAD} = 100\text{ mA}$ to $300\text{ mA}$ to $100\text{ mA}$ ( $0.2\text{ A}/\mu\text{s}$ ); Buck $V_{IN} = 3.6\text{ V}$ , Buck $V_{OUT} = 1.2\text{ V}$ .....	23
Figure 33: Buck $I_{LOAD} = 10\text{ mA}$ to $300\text{ mA}$ to $10\text{ mA}$ ( $0.3\text{ A}/\mu\text{s}$ ); Buck $V_{IN} = 3.6\text{ V}$ , Buck $V_{OUT} = 0.9\text{ V}$ 23	
Figure 34: Buck $I_{LOAD} = 100\text{ mA}$ to $300\text{ mA}$ to $100\text{ mA}$ ( $0.2\text{ A}/\mu\text{s}$ ); Buck $V_{IN} = 3.6\text{ V}$ , Buck $V_{OUT} = 0.9\text{ V}$ .....	23
Figure 35: Buck $I_{LOAD} = 10\text{ mA}$ to $300\text{ mA}$ to $10\text{ mA}$ ( $0.3\text{ A}/\mu\text{s}$ ); Buck $V_{IN} = 3.6\text{ V}$ , Buck $V_{OUT} = 0.6\text{ V}$ 24	
Figure 36: Buck $I_{LOAD} = 100\text{ mA}$ to $300\text{ mA}$ to $100\text{ mA}$ ( $0.2\text{ A}/\mu\text{s}$ ); Buck $V_{IN} = 3.6\text{ V}$ , Buck $V_{OUT} = 0.6\text{ V}$ .....	24
Figure 37: Buck $V_{OUT} 0.6\text{ V}$ to $1.2\text{ V}$ ; Buck $V_{IN} = 3.6\text{ V}$ , Buck $I_{LOAD} = 300\text{ mA}$ .....	25
Figure 38: Buck $V_{OUT} 1.2\text{ V}$ to $0.6\text{ V}$ ; Buck $V_{IN} = 3.6\text{ V}$ , Buck $I_{LOAD} = 300\text{ mA}$ .....	25
Figure 39: Buck $V_{OUT} 1.3\text{ V}$ to $1.9\text{ V}$ ; Buck $V_{IN} = 3.6\text{ V}$ , Buck $I_{LOAD} = 300\text{ mA}$ .....	25
Figure 40: Buck $V_{OUT} 1.9\text{ V}$ to $1.3\text{ V}$ ; Buck $V_{IN} = 3.6\text{ V}$ , Buck $I_{LOAD} = 300\text{ mA}$ .....	25
Figure 41: Device Enable: Buck $V_{IN} = 3.6\text{ V}$ , Buck $V_{OUT} 1.8\text{ V}$ , Buck $I_{LOAD} = 300\text{ mA}$ .....	26
Figure 42: $V_{OUT}$ ramp-up after Enabled (Zoom-in of Figure 41) .....	26
Figure 43: I <sup>2</sup> C Serial Interface Pins .....	31
Figure 44: I <sup>2</sup> C Start and Stop Conditions .....	31
Figure 45: Package Outline Drawing .....	44

## Tables

Table 1: Pin Description .....	8
Table 2: Pin Type Definition .....	9
Table 3: Absolute Maximum Ratings .....	10
Table 4: Recommended Operating Conditions .....	11
Table 5: Input Current .....	13
Table 6: Buck Output .....	13
Table 7: GPO - Electrical performance .....	14
Table 8: Analog Core - Electrical performance .....	14
Table 9: I <sup>2</sup> C interface .....	15
Table 10: Thermal Characteristics .....	16
Table 11: Buck Output Voltage Settings .....	27
Table 12: GPO as Power Good Indicator .....	32
Table 13: Event/Status/Mask and User Registers .....	33
Table 14: System Reset Registers .....	34
Table 15: Register EVENT .....	34
Table 16: Register STATUS .....	35
Table 17: Register MASK .....	36
Table 18: Register GPO .....	36
Table 19: Register BUCK .....	37

---

**Ultra-Low Quiescent Current Buck**

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Table 20: Register BUCK_CFG .....	39
Table 21: Register FAUL_CTL .....	40
Table 22: Register PIN_MONITOR .....	41
Table 23: Register SYS_RST_EVENT .....	41
Table 24: Register SYS_SRST .....	41
Table 25: Register SYS_DEVICE_ID .....	42
Table 26: Register SYS_VARIANT_ID .....	42
Table 27: Register SYS_CONFIG_ID .....	43
Table 28: MSL Classification .....	45
Table 29: Ordering Information .....	46
Table 30: OTP List.....	46

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## Ultra-Low Quiescent Current Buck

### 1 Terms and Definitions

CDM	Charged Device Model
DC	Direct Current
DCM	Discontinuous Conduction Mode
FET	Field Effect Transistor
NMOS	N-channel Metal-Oxide-Semiconductor
OTP	One-Time Programmable (memory)
PMIC	Power Management IC
PMOS	P-channel Metal-Oxide-Semiconductor
R/W	Read/Write
SCL	Serial CLock SDA
T&R	Tape and Reel
UVLO	Under-Voltage LockOut
WLCSP	Wafer-Level Chip-Scale Package

Ultra-Low Quiescent Current Buck

2 Block and Application Diagrams

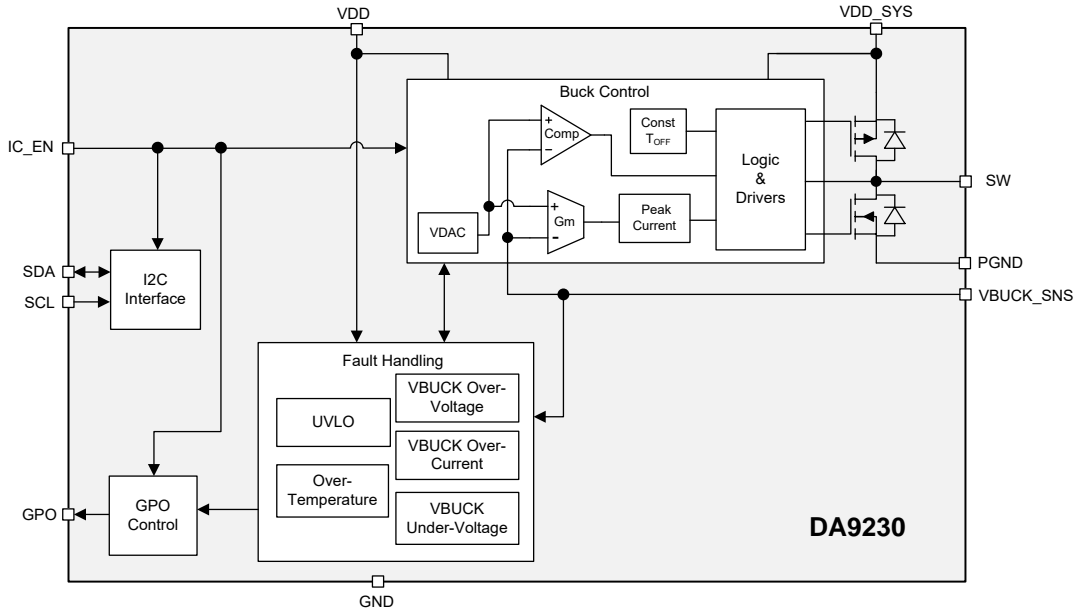


Figure 1: Block Diagram

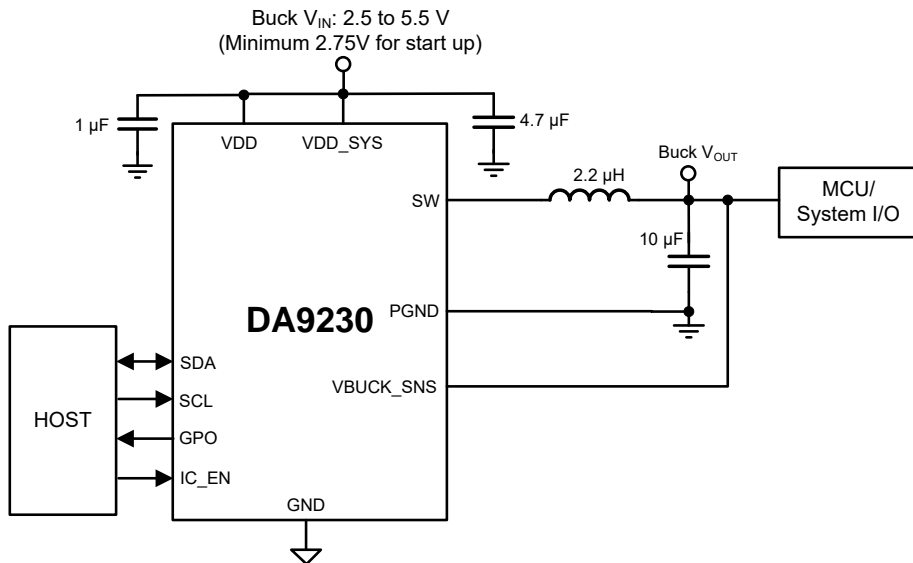


Figure 2: DA9230 Application Diagram

## Ultra-Low Quiescent Current Buck

### 3 Pinout

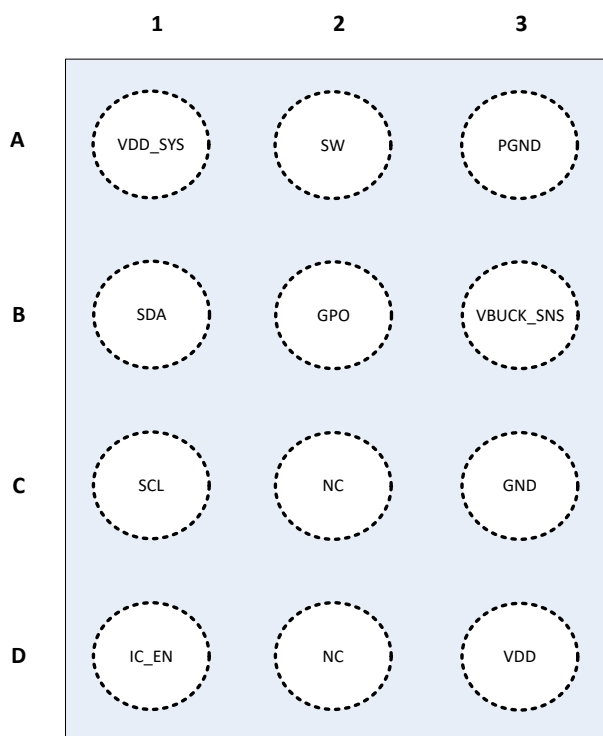


Figure 3: Pinout Diagram (Top View)

Table 1: Pin Description

Pin #	Pin Name	Type (See Table 2)	Drive (mA)	Reset State	Description
A1	VDD_SYS	AI			Buck $V_{IN}$
A2	SW	AIO			Buck switch node
A3	PGND	AIO			Buck ground
B1	SDA	DIO			I <sup>2</sup> C serial data
B2	GPO	DO			General purpose output
B3	VBUCK_SNS	AI			Buck $V_{OUT}$ /feedback voltage
C1	SCL	DI			I <sup>2</sup> C serial clock
C2	NC				No connection
C3	GND	AI			Analog ground
D1	IC_EN	DI			Chip enable
D2	NC				No connection
D3	VDD	AI			Analog $V_{IN}$



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## Ultra-Low Quiescent Current Buck

**Table 2: Pin Type Definition**

Pin Type	Description	Pin Type	Description
DI	Digital Input	AI	Analog Input
DO	Digital Output	AO	Analog Output
DIO	Digital Input/Output	AIO	Analog Input/Output
DIOD	Digital Input/Output open Drain	BP	Back drive Protection
PU	Fixed pull-up resistor	SPU	Switchable pull-up resistor
PD	Fixed pull-down resistor	SPD	Switchable pull-down resistor

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## Ultra-Low Quiescent Current Buck

### 4 Absolute Maximum Ratings

**Table 3: Absolute Maximum Ratings**

Symbol	Description	Conditions	Min	Max	Unit
T <sub>STG</sub>	Storage temperature		-40	125	°C
T <sub>J</sub>	Operating junction temperature		40	125	°C
VDD	Analog V <sub>IN</sub> pin	Tied to VDD_SYS	-0.3	6	V
VDD_SYS	Power V <sub>IN</sub> pin	Tied to VDD	-0.3	6	V
I/O pins	Maximum voltage	I/O pin voltage ≤ VDD	-0.3	6	V

Stresses beyond those listed under Absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, so functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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## Ultra-Low Quiescent Current Buck

### 5 Recommended Operating Conditions

**Table 4: Recommended Operating Conditions**

Parameter	Description	Conditions	Min	Typ	Max	Unit
VDD	Analog $V_{IN}$	Tied to VDD_SYS	2.5 <a href="#">Note 1</a>		5.5	V
VDD_SYS	Power $V_{IN}$	Tied to VDD	2.5 <a href="#">Note 1</a>		5.5	V
I <sub>OUT_BUCK</sub>	Buck load Current	Output current from SW pin, continuous DC current			300	mA

**Note 1** Requires minimum 2.75V for start-up. Once started, input voltage can go down to 2.5V.

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**Ultra-Low Quiescent Current Buck**

## 6 ESD Ratings

Parameter	Description	Conditions	Value	Unit
V <sub>ESD</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 <a href="#">Note 1</a>	± 2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101 <a href="#">Note 2</a>	± 500	

**Note 1** JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

**Note 2** JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

## Ultra-Low Quiescent Current Buck

### 7 Electrical Characteristics

VDD = VDD\_SYS = 3.6 V, T<sub>J</sub> = -40°C to 85°C. Typical values are at T<sub>J</sub> = 25°C (unless otherwise noted).

**Table 5: Input Current**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Electrical performance</b>						
I <sub>Q_BUCK_ON_NO_LD</sub>	Buck no load quiescent current	-40 °C < T <sub>J</sub> < 85 °C Buck enabled and regulating, no load 2.5 V ≤ V <sub>VDD_SYS</sub> ≤ 5.5 V V <sub>BUCK</sub> = 1.8 V		0.75	3.5	μA

**Table 6: Buck Output**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Electrical performance</b>						
R <sub>ON_PMOS</sub>	On resistance of PMOS pass device	V <sub>VDD_SYS</sub> = 3.6 V I <sub>OUT</sub> = 50 mA		600	800	mΩ
R <sub>ON_NMOS</sub>	On resistance of NMOS pass device	V <sub>VDD_SYS</sub> = 3.6 V I <sub>OUT</sub> = 50 mA		300	450	mΩ
R <sub>SYS_DHCG</sub>	MOSFET on-resistance for buck discharge	V <sub>VDD_SYS</sub> = 3.6 V I <sub>OUT</sub> = -10 mA into V <sub>OUT</sub> pin		33		Ω
t <sub>START</sub>	Buck start-up time	V <sub>VDD_SYS</sub> = 3.6 V V <sub>BUCK</sub> = 1.8 V I <sub>OUT</sub> = 0 A from BUCK_EN = 1 to switching start		3		ms
I <sub>LIM_SW_PMOS</sub>	SW current limit PMOS	V <sub>VDD_SYS</sub> = 3.6 V V <sub>BUCK</sub> = 1.8 V		600		mA
t <sub>OFF</sub>	Off time in continuous conduction mode	V <sub>BUCK</sub> = 1.8 V		270		ns
f <sub>SW</sub>	Switching frequency in continuous conduction mode				3	MHz
I <sub>OUT_MAX</sub>	Maximum DC output current		300			mA
I <sub>LIM_PMOS_SOFTSTART</sub>	PMOS switch current limit during softstart	Current limit is reduced during softstart		350		mA
V <sub>OUT_VBUCK_SNS</sub>	Buck output voltage range	Programable range, 50 mV steps	0.6		1.9	V

## Ultra-Low Quiescent Current Buck

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>OUT_VBUC</sub> K_SNS_HI	Buck output voltage range	HI programable range, 50 mV steps V <sub>OUT_RANGE_HI</sub> = 1	1.3		1.9	V
V <sub>OUT_VBUC</sub> K_SNS_LO	Buck output voltage range	LO programable range, 50 mV steps V <sub>OUT_RANGE_HI</sub> = 0	0.6		1.3	V
V <sub>OUT_VBUC</sub> K_ACC	Buck output voltage accuracy	V <sub>VDD_SYS</sub> = 5 V PFM mode I <sub>OUT</sub> = 10 mA V <sub>OUT_RANGE_HI</sub> = 1 V <sub>BUCK</sub> = 1.8 V	-2.5	0	2.5	%
V <sub>OUT_PWM</sub> _LD2	DC output voltage load regulation in CCM mode	V <sub>BUCK</sub> = 1.8 V Load range		0.01		%/mA
V <sub>OUT_PWM</sub> _LINE2	DC output voltage line regulation in CCM mode	V <sub>BUCK</sub> = 1.8 V I <sub>OUT</sub> = 200 mA V <sub>DD</sub> range		0.1		%/V

**Table 7: GPO - Electrical performance**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R <sub>PD</sub>	GPO pull-down resistance	V <sub>VDD_SYS</sub> = 3.6 V		12		Ω
V <sub>OH</sub>	GPO Output high voltage	V <sub>PULLUP</sub> = 1.8 V	1.4			V
V <sub>OL</sub>	GPO Output low voltage	V <sub>PULLUP</sub> = 1.8 V			0.4	V

**Table 8: Analog Core - Electrical performance**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
T <sub>SHDN_HYS</sub>	Thermal shut-down hysteresis			20		°C
T <sub>SHDN_THR</sub>	Thermal shut-down threshold			125		°C
V <sub>TH_UVLO</sub>	Under-voltage lockout threshold	Input voltage falling	2.4		2.5	V
V <sub>TH_UVLO</sub> RISE	Under-voltage lockout threshold rising.	Input voltage rising.			2.75	V
V <sub>HYS_UVLO</sub>	Under-voltage lockout hysteresis	Input voltage rising		200		mV

## Ultra-Low Quiescent Current Buck

**Table 9: I2C interface**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Electrical performance</b>						
f <sub>I2C_CLK</sub>	I <sup>2</sup> C bus specification standard and fast mode frequency support		100		400	kHz
V <sub>IN_HI_THR</sub>	Input high threshold level for SDA and SCL		1.4			V
V <sub>IN_LO_THR</sub>	Input low threshold level for SDA and SCL				0.4	V
V <sub>OUT_LO_THR</sub>	Output low threshold level for SDA				0.4	V
I <sub>LKG_HILVL</sub>	High-level leakage current for SDA and SCL.	V <sub>PU</sub> = V <sub>VDD</sub> SDA and SCL			1	μA

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## Ultra-Low Quiescent Current Buck

### 8 Thermal Characteristics

**Table 10: Thermal Characteristics**

Parameter	Description	Conditions	Typ	Unit
R <sub>TH_JA</sub>	Junction-to-ambient thermal resistance	JEDEC 6-layer pcb, no airflow	73.2	°C/W
Ψ <sub>JT</sub>	Junction-to-top characterization parameter	JEDEC 6-layer pcb, no airflow	6.66	°C/W
R <sub>TH_JB</sub>	Junction-to-board thermal resistance	JEDEC 6-layer pcb, no airflow	34.8	°C/W



Ultra-Low Quiescent Current Buck

9 Typical Operating Characteristics

Test Circuit of Figure 2, Buck  $V_{IN} = VDD\_SYS = VDD$ ,  $L=2.2 \mu H$  (170 m $\Omega$ ),  $T_A = 25^\circ C$ , unless specified otherwise.

9.1 Buck No Load Quiescent Current vs Temperature, Device is Switching

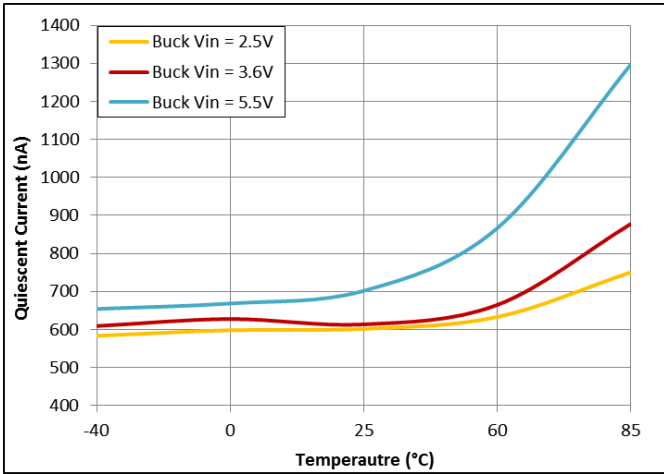


Figure 4: Buck  $V_{OUT} = 1.8 V$

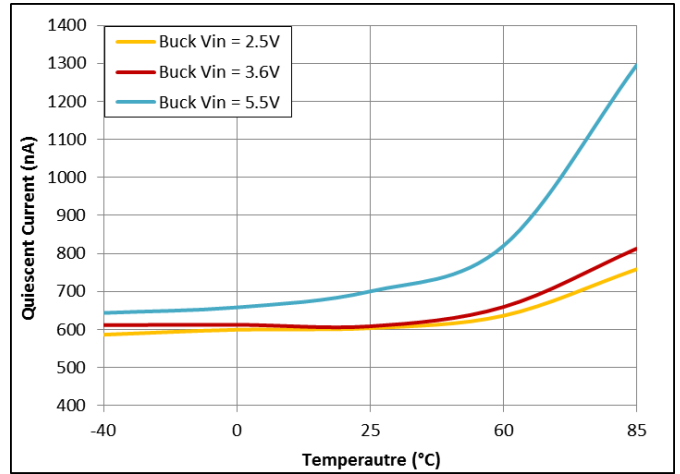


Figure 5: Buck  $V_{OUT} = 0.9 V$

9.2 RDSon vs Temperature

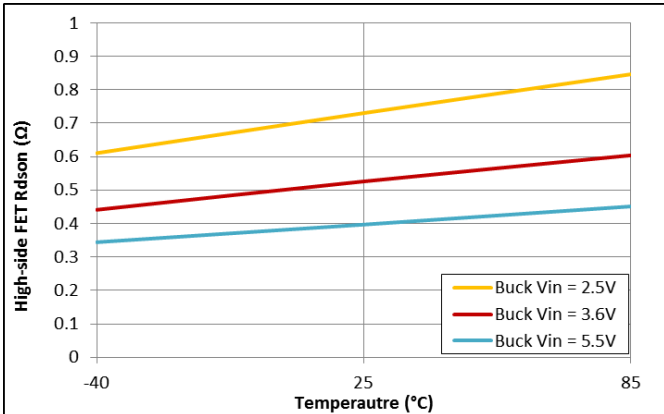


Figure 6: High-Side FET

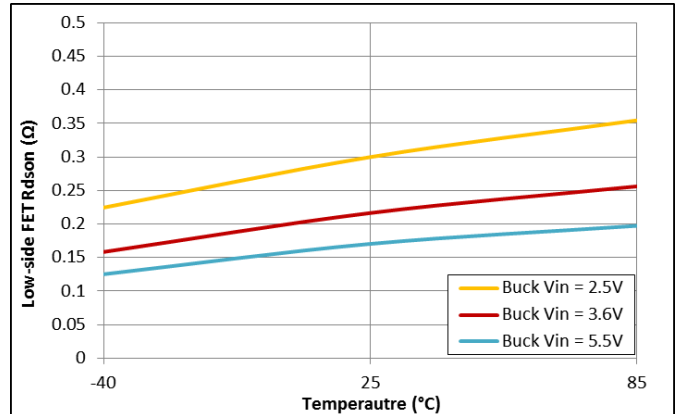


Figure 7: Low-Side FET

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9.3 Efficiency vs Load Current

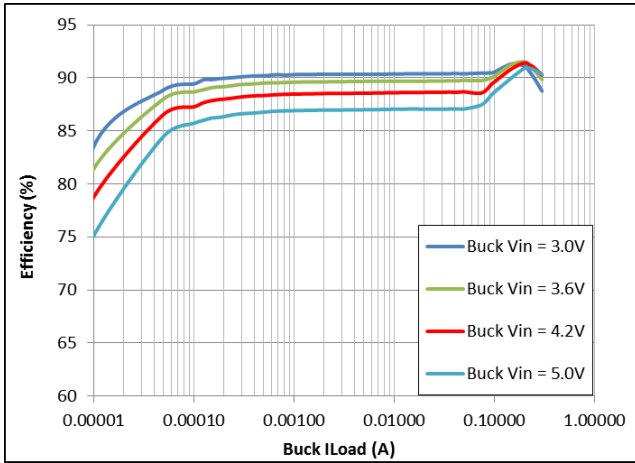


Figure 8: Buck V<sub>OUT</sub> = 1.9 V

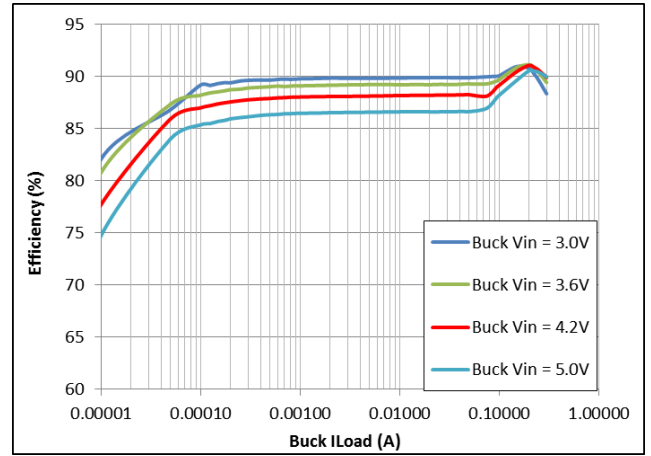


Figure 9: Buck V<sub>OUT</sub> = 1.8 V

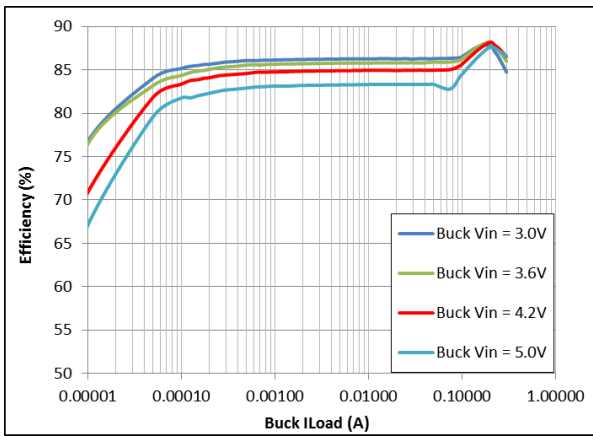


Figure 10: Buck V<sub>OUT</sub> = 1.2 V

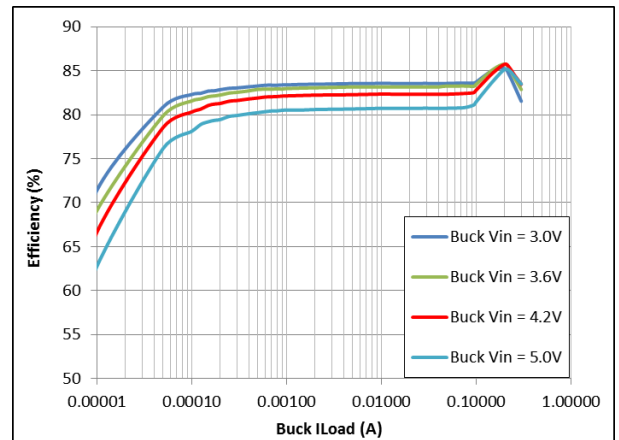


Figure 11: Buck V<sub>OUT</sub> = 0.9 V

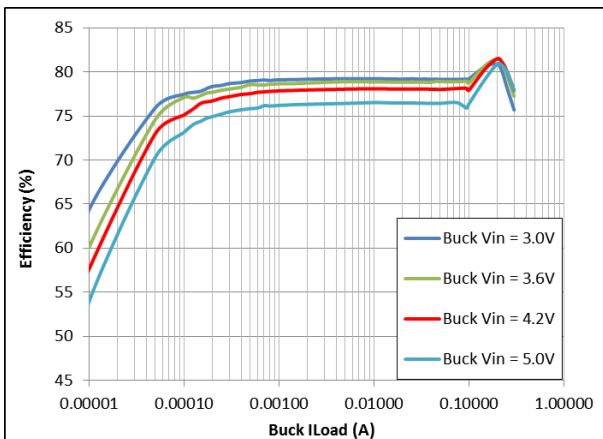


Figure 12: Buck V<sub>OUT</sub> = 0.6 V

Ultra-Low Quiescent Current Buck

9.4 Switching Frequency vs Load Current

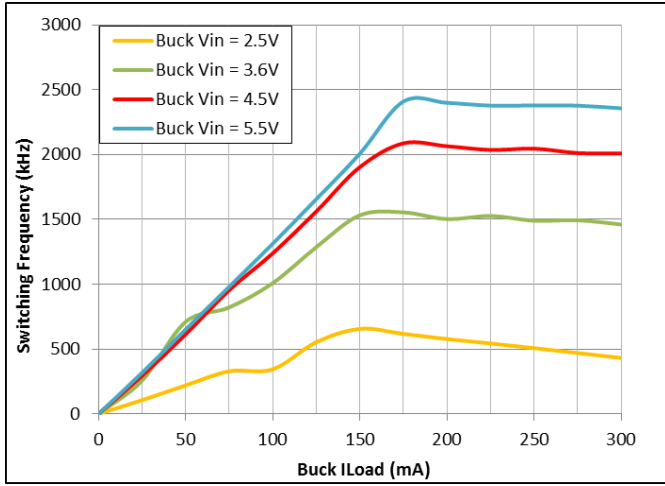


Figure 13: Buck V<sub>OUT</sub> = 1.9 V

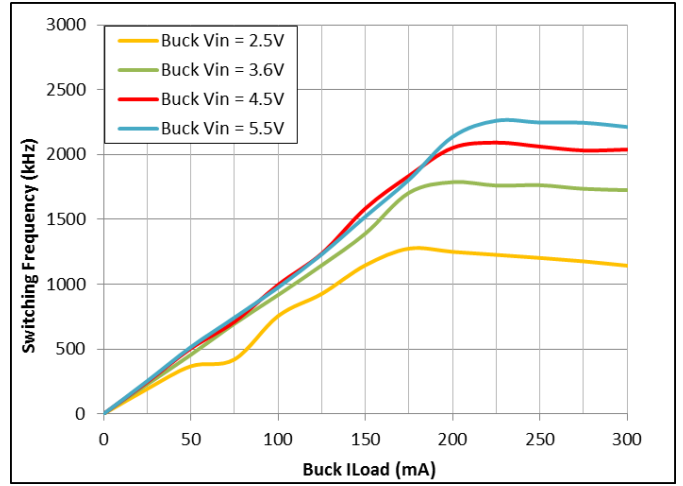


Figure 15: Buck V<sub>OUT</sub> = 1.2 V

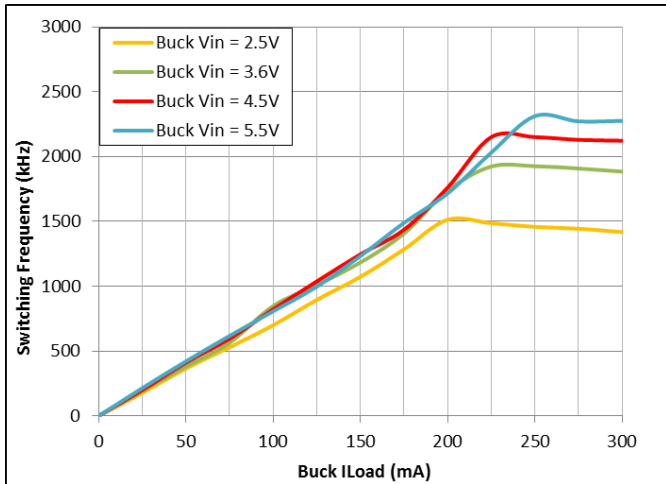


Figure 14: Buck V<sub>OUT</sub> = 0.9 V

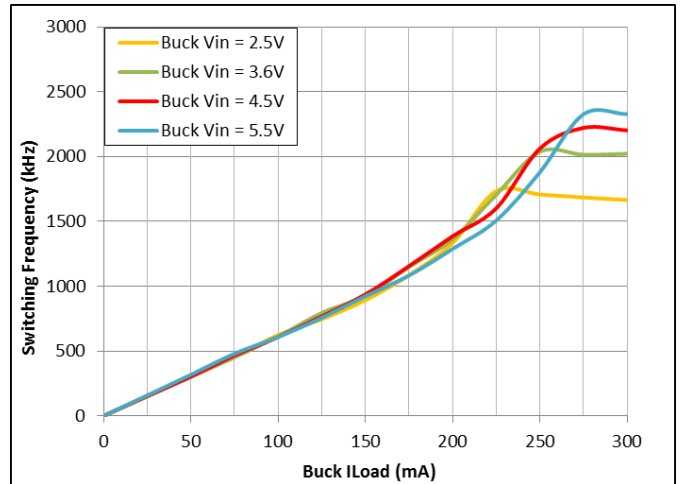


Figure 16: Buck V<sub>OUT</sub> = 0.6 V

Ultra-Low Quiescent Current Buck

9.5 Buck V<sub>OUT</sub> Ripple vs Load Current

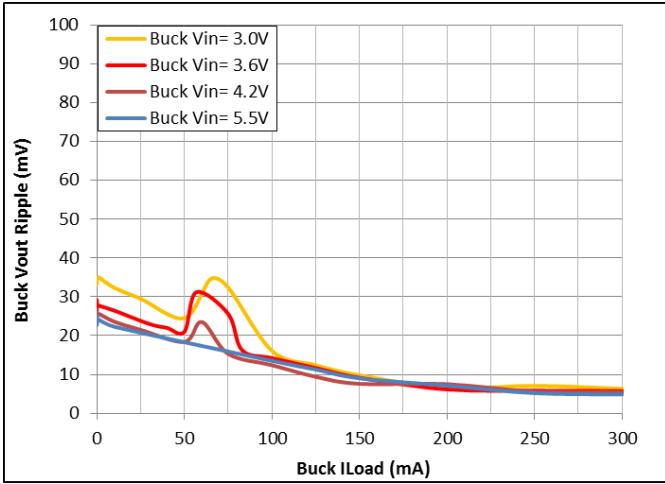


Figure 17: Buck V<sub>OUT</sub> = 1.9 V

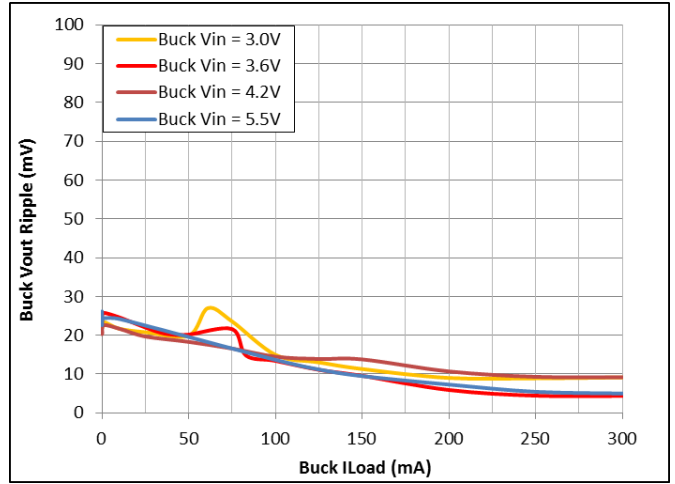


Figure 18: Buck V<sub>OUT</sub> = 1.3 V

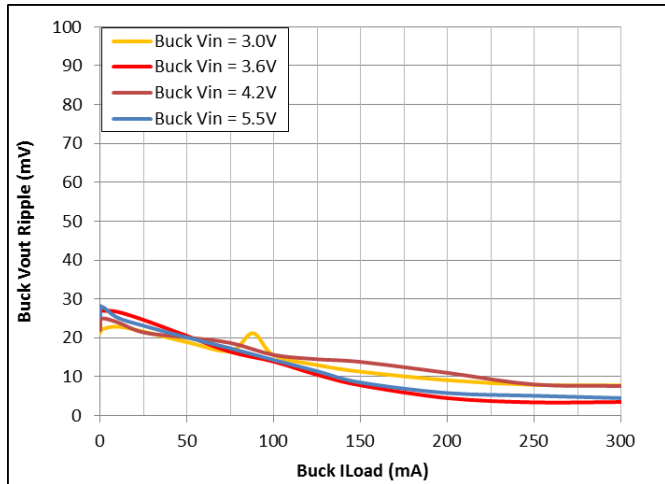


Figure 19: Buck V<sub>OUT</sub> = 0.9 V

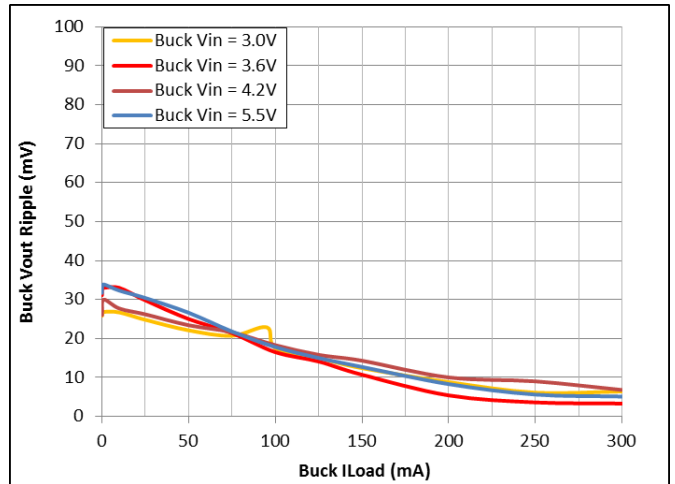


Figure 20: Buck V<sub>OUT</sub> = 0.6 V

Ultra-Low Quiescent Current Buck

9.6 Buck  $V_{OUT}$  vs Load Current

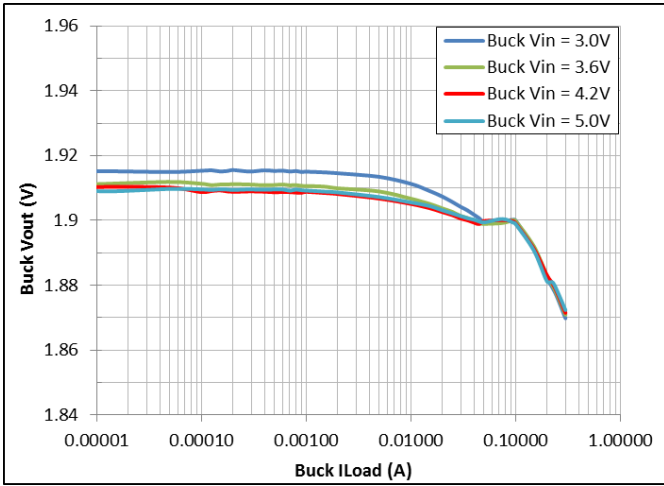


Figure 21: Buck  $V_{OUT} = 1.9\text{ V}$

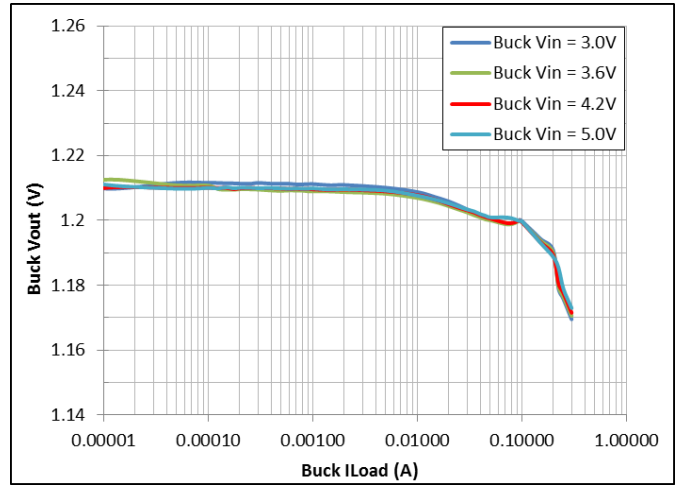


Figure 22: Buck  $V_{OUT} = 1.2\text{ V}$

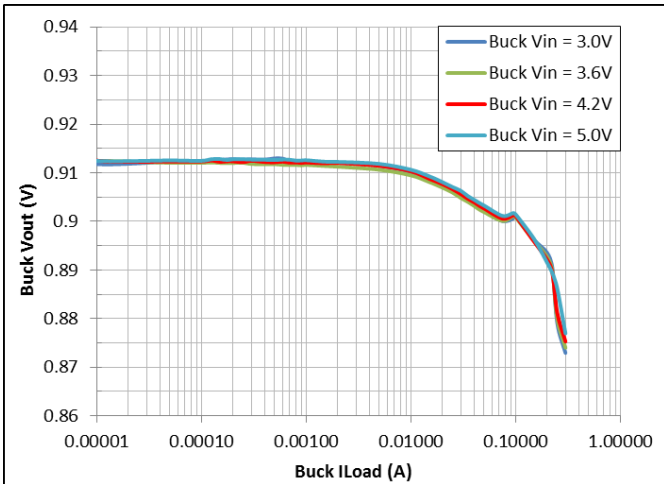


Figure 23: Buck  $V_{OUT} = 0.9\text{ V}$

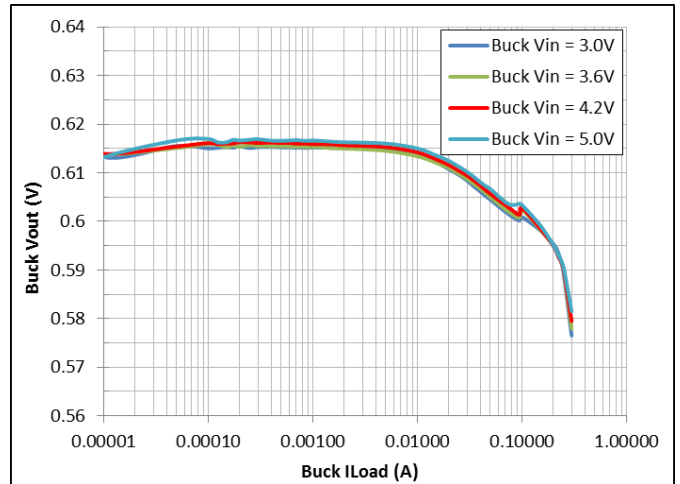
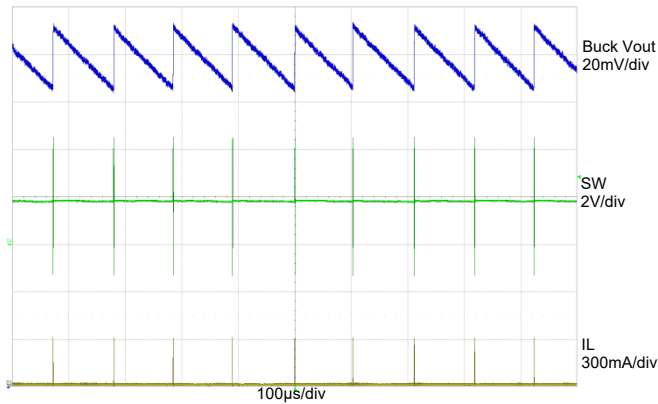


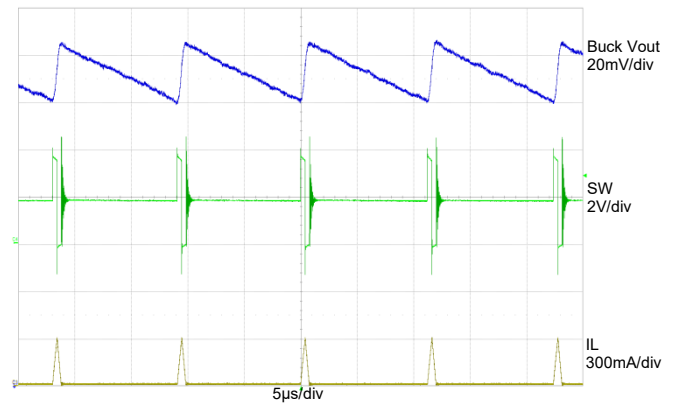
Figure 24: Buck  $V_{OUT} = 0.6\text{ V}$

## Ultra-Low Quiescent Current Buck

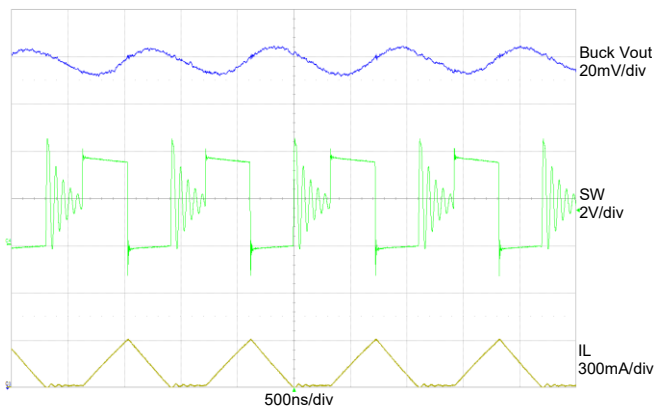
### 9.7 Typical Mode Operation



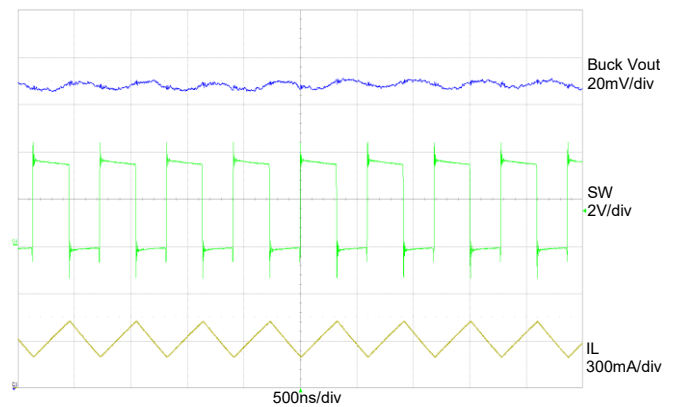
**Figure 25: Buck  $V_{IN} = 3.6$  V, Buck  $V_{OUT} = 1.8$  V,  
Buck  $I_{LOAD} = 1$  mA**



**Figure 26: Buck  $V_{IN} = 3.6$  V, Buck  $V_{OUT} = 1.8$  V,  
Buck  $I_{LOAD} = 10$  mA**



**Figure 27: Buck  $V_{IN} = 3.6$  V, Buck  $V_{OUT} = 1.8$  V,  
Buck  $I_{LOAD} = 100$  mA**



**Figure 28: Buck  $V_{IN} = 3.6$  V, Buck  $V_{OUT} = 1.8$  V,  
Buck  $I_{LOAD} = 300$  mA**

Ultra-Low Quiescent Current Buck

9.8 Buck Load Transient Response

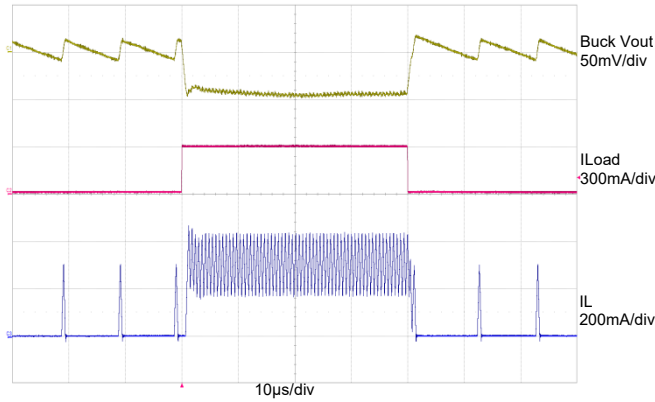


Figure 29: Buck  $I_{LOAD} = 10\text{ mA}$  to  $300\text{ mA}$  to  $10\text{ mA}$  ( $0.3\text{ A}/\mu\text{s}$ ); Buck  $V_{IN} = 3.6\text{ V}$ , Buck  $V_{OUT} = 1.8\text{ V}$

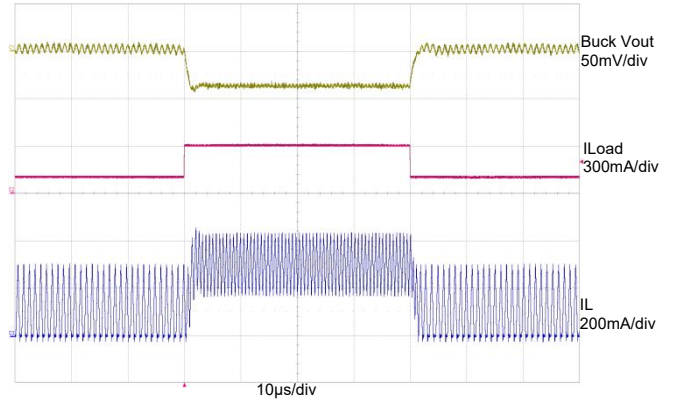


Figure 30: Buck  $I_{LOAD} = 100\text{ mA}$  to  $300\text{ mA}$  to  $100\text{ mA}$  ( $0.2\text{ A}/\mu\text{s}$ ); Buck  $V_{IN} = 3.6\text{ V}$ , Buck  $V_{OUT} = 1.8\text{ V}$

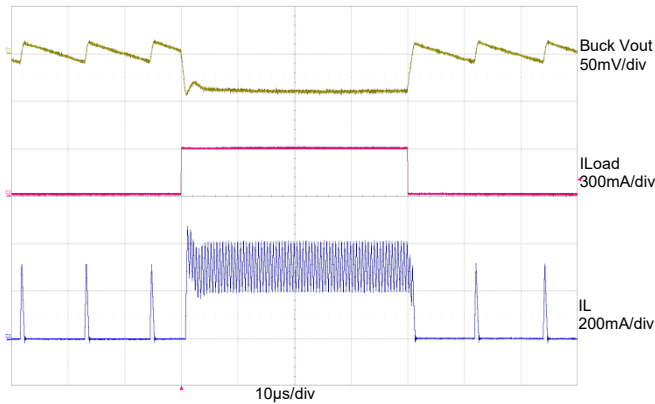


Figure 31: Buck  $I_{LOAD} = 10\text{ mA}$  to  $300\text{ mA}$  to  $10\text{ mA}$  ( $0.3\text{ A}/\mu\text{s}$ ); Buck  $V_{IN} = 3.6\text{ V}$ , Buck  $V_{OUT} = 1.2\text{ V}$

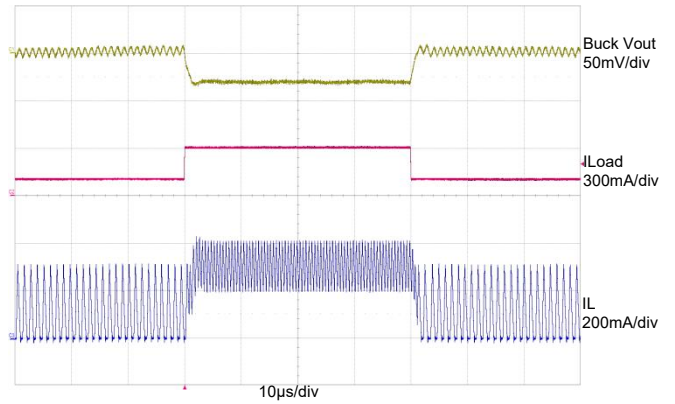


Figure 32: Buck  $I_{LOAD} = 100\text{ mA}$  to  $300\text{ mA}$  to  $100\text{ mA}$  ( $0.2\text{ A}/\mu\text{s}$ ); Buck  $V_{IN} = 3.6\text{ V}$ , Buck  $V_{OUT} = 1.2\text{ V}$

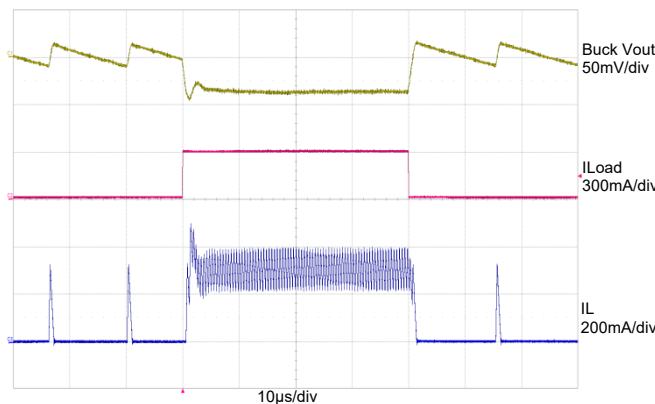


Figure 33: Buck  $I_{LOAD} = 10\text{ mA}$  to  $300\text{ mA}$  to  $10\text{ mA}$  ( $0.3\text{ A}/\mu\text{s}$ ); Buck  $V_{IN} = 3.6\text{ V}$ , Buck  $V_{OUT} = 0.9\text{ V}$

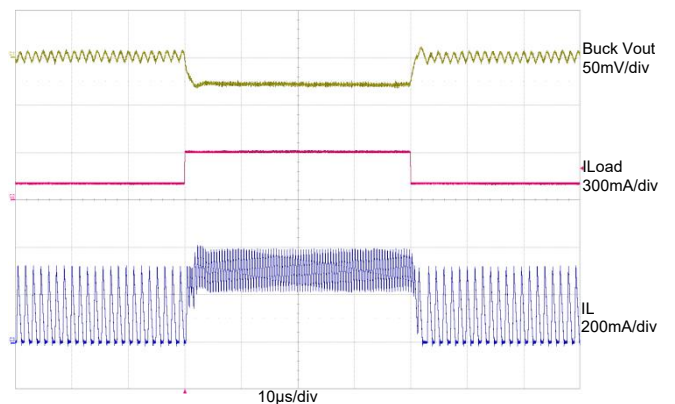
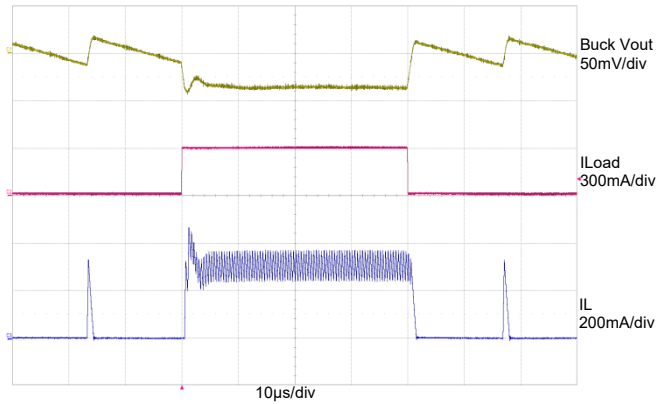
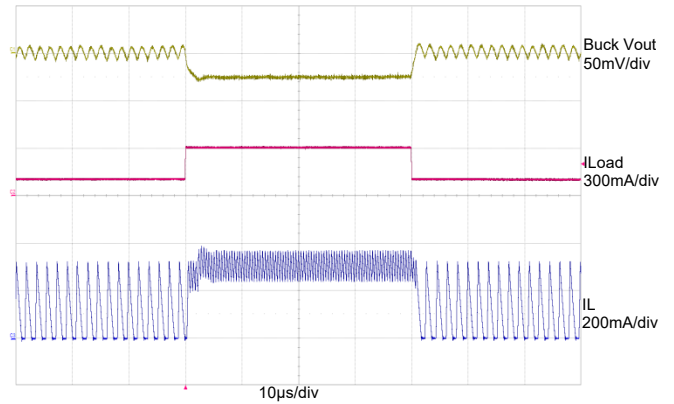


Figure 34: Buck  $I_{LOAD} = 100\text{ mA}$  to  $300\text{ mA}$  to  $100\text{ mA}$  ( $0.2\text{ A}/\mu\text{s}$ ); Buck  $V_{IN} = 3.6\text{ V}$ , Buck  $V_{OUT} = 0.9\text{ V}$

## Ultra-Low Quiescent Current Buck



**Figure 35:** Buck  $I_{LOAD} = 10 \text{ mA}$  to  $300 \text{ mA}$  to  $10 \text{ mA}$  ( $0.3 \text{ A}/\mu\text{s}$ ); Buck  $V_{IN} = 3.6 \text{ V}$ , Buck  $V_{OUT} = 0.6 \text{ V}$

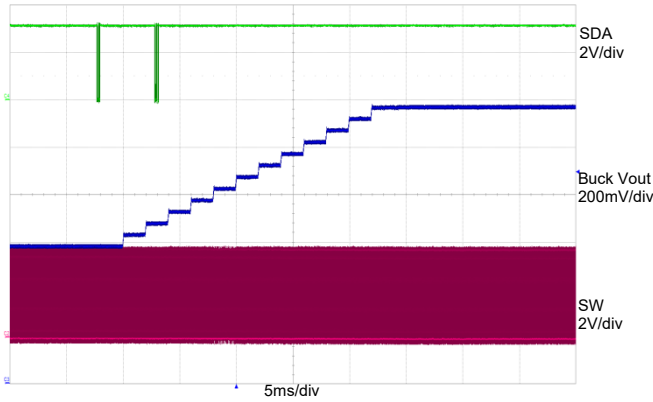


**Figure 36:** Buck  $I_{LOAD} = 100 \text{ mA}$  to  $300 \text{ mA}$  to  $100 \text{ mA}$  ( $0.2 \text{ A}/\mu\text{s}$ ); Buck  $V_{IN} = 3.6 \text{ V}$ , Buck  $V_{OUT} = 0.6 \text{ V}$

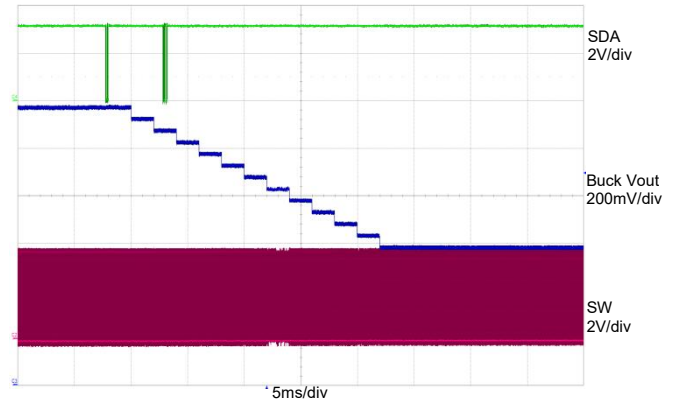


Ultra-Low Quiescent Current Buck

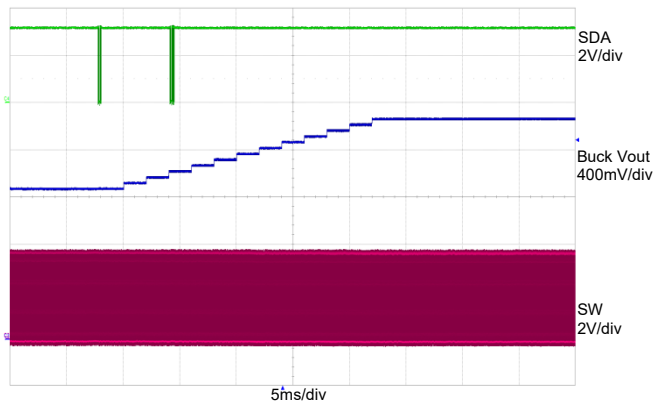
9.9 Buck Dynamic Voltage Control



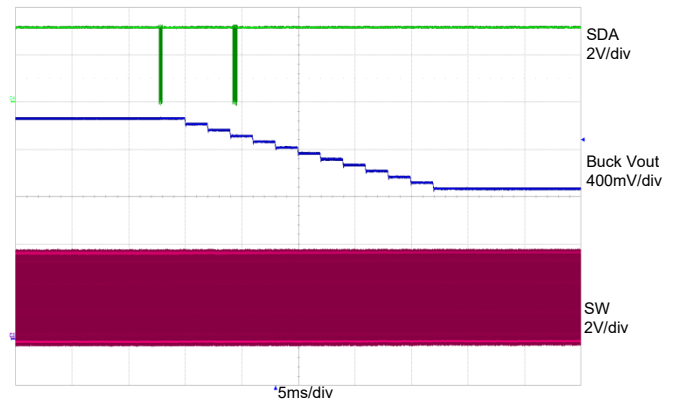
**Figure 37: Buck  $V_{OUT}$  0.6 V to 1.2 V;  
Buck  $V_{IN}$  = 3.6 V, Buck  $I_{LOAD}$  = 300 mA**



**Figure 38: Buck  $V_{OUT}$  1.2 V to 0.6 V;  
Buck  $V_{IN}$  = 3.6 V, Buck  $I_{LOAD}$  = 300 mA**



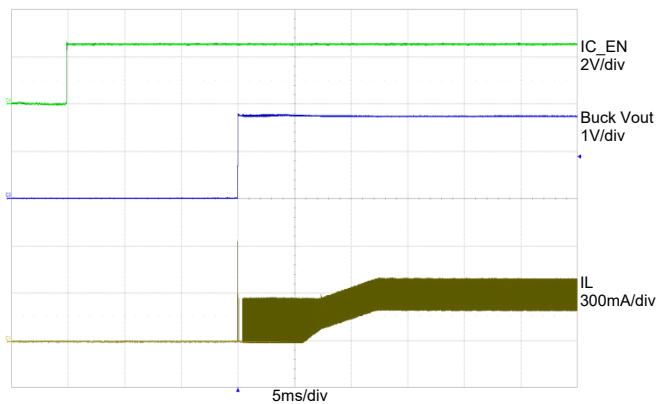
**Figure 39: Buck  $V_{OUT}$  1.3 V to 1.9 V;  
Buck  $V_{IN}$  = 3.6 V, Buck  $I_{LOAD}$  = 300 mA**



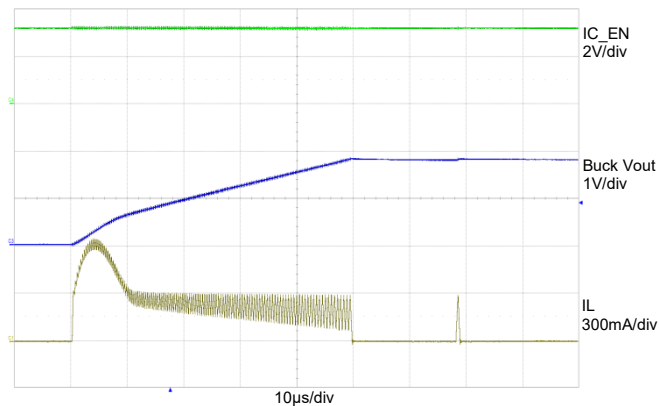
**Figure 40: Buck  $V_{OUT}$  1.9 V to 1.3 V;  
Buck  $V_{IN}$  = 3.6 V, Buck  $I_{LOAD}$  = 300 mA**

Ultra-Low Quiescent Current Buck

9.10 Device Enable and Start up



**Figure 41: Device Enable:**  
 Buck  $V_{IN} = 3.6\text{ V}$ , Buck  $V_{OUT} 1.8\text{ V}$ ,  
 Buck  $I_{LOAD} = 300\text{ mA}$



**Figure 42:  $V_{OUT}$  ramp-up after Enabled**  
 (Zoom-in of [Figure 41](#))

## Ultra-Low Quiescent Current Buck

# 10 Feature Descriptions

## 10.1 Chip Enable and Disable Through IC\_EN

DA9230 features a dedicated IC\_EN pin to enable and disable the chip. When IC\_EN = high, the device is turned on. IC\_EN voltage should not exceed VDD\_SYS voltage on the device. When EN = low, the device is shut down completely, including I<sup>2</sup>C communications.

## 10.2 VDD Under-Voltage Lockout

DA9230 features an under-voltage lockout (UVLO) on VDD. When VDD falls below UVLO falling threshold, buck is disabled, see Section 10.4.9 for fault behaviour and control, A VIN\_UV\_Event will be flagged if it is not masked. When VDD rises above the UVLO rising threshold, the device will be alive. VDD should be always tied to VDD\_SYS on the PCB board so both VDD and VDD\_SYS will share the same UVLO protection.

## 10.3 Over-Temperature Protection

DA9230 also features an on-Chip over-temperature protection (TSD). The die junction temperature is monitored when buck is in continuous current Mode. When the junction temperature is higher than the thermal shutdown threshold, buck is disabled to prevent the device being damaged by over-heating, see Section 10.4.9 for fault behavior and control. An OT\_Event will be flagged if it is not masked.

## 10.4 Buck Regulator

DA9230 includes a nano-ampere standby buck regulator with an adjustable output voltage, Dynamic Voltage Scaling capability and a maximum load current of 300 mA. It also has power saving mode operation and different protection features.

### 10.4.1 Buck Output Voltage Programability

The DA9230 buck regulator can be set to two different ranges based on the value of VOUT\_RANGE\_HI. The value of BUCK\_VOUT<4:0> is locked to a certain range based on the value of VOUT\_RANGE\_HI, and VOUT\_RANGE\_HI can only be changed while the buck is disabled. The buck can be set to the output voltages shown in Table 11. If a command is received outside of the allowable range (that is above 1.3 V for VOUT\_RANGE\_HI = 0 or below 1.3 V for VOUT\_RANGE\_HI = 1), digital will force the value of BUCK\_VOUT<3:0> to 01110 (1.3 V).

**Table 11: Buck Output Voltage Settings**

VOUT_RANGE_HI	BUCK_VOUT<4:0>	Buck Output Voltage (V)
0	00000	0.60
0	00001	0.65
0	00010	0.70
0	00011	0.75
0	00100	0.80
0	00101	0.85
0	00110	0.90
0	00111	0.95

## Ultra-Low Quiescent Current Buck

VOUT_RANGE_HI	BUCK_VOUT<4:0>	Buck Output Voltage (V)
0	01000	1.00
0	01001	1.05
0	01010	1.10
0	01011	1.15
0	01100	1.20
0	01101	1.25
0 or 1	01110	1.30
1	01111	1.35
1	10000	1.40
1	10001	1.45
1	10010	1.50
1	10011	1.55
1	10100	1.60
1	10101	1.65
1	10110	1.70
1	10111	1.75
1	11000	1.80
1	11001	1.85
1	11010	1.90
1	11011	1.90
1	11100	1.90
1	11101	1.90
1	11110	1.90
1	11111	1.90

### 10.4.2 Start-up Operation

DA9230 buck integrates a start-up circuit to minimize output voltage over-shoot and input voltage drop during start-up. When writing 1 to BUCK\_EN (Bit 7 of Reg0x05), the buck is enabled and starts switching after a typical delay time of 3 ms. During start-up, the cycle-by-cycle current limit is reduced to limit inrush current.

### 10.4.3 Power Saving Mode Operation

DA9230 buck regulator features power saving mode that greatly reduces the quiescent current when device has very light load condition. When load decreases, buck regulator enters discontinuous mode and operates with Pulse Frequency Modulation (PFM). The low-side FET will be turned off based on a zero-crossing comparator to prevent negative inductor current flowing through the FET which can result in additional conduction loss. If both FETs remain in the OFF state for a certain delay time after inductor current crosses zero, the device will enter power saving mode. In power saving mode, DA9230 shuts down most of the internal circuitry to save current consumption. The

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## Ultra-Low Quiescent Current Buck

lighter the load, the longer the duration of power saving mode will be, to achieve the lowest quiescent current and improve light load efficiency.

### 10.4.4 Dynamic Voltage Control

DA9230 buck regulator has dynamic voltage control (DVC) feature which allows the buck output voltage to track the internal reference voltage when it changes at a rate of 50 mV/2 ms. Since the buck output voltage can only be changed within an allowable range while still keeping the buck enabled, DVC also follows the same behaviour. The DVC is done via I<sup>2</sup>C, whereby the buck output voltage setting is stepped in 50 mV steps within either the low range or high range. Each voltage step lasts for 2 ms.

### 10.4.5 Cycle-by-cycle Over-Current Protection

For the Over-current Protection (OCP) in DA9230, the peak current through high-side FET is monitored cycle-by-cycle. When the sensed current exceeds the pre-set current limit, the high-side FET will be turned OFF immediately to limit the inductor current. The high-side FET will be turned on again after the constant-off time expires. If the OC condition persists for 64  $\mu$ s, buck will be forced off and buck output will be pull-down until the fault clears, see Section 10.4.9 for fault behavior and control and Section 10.4.8 for output voltage discharge and control. An OC\_BUCK\_Event will be flagged if it is not masked.

### 10.4.6 Output Over-Voltage Protection

DA9230 features an output over-voltage protection (OVP) to protect the load from damage. When both IC\_EN and BUCK\_EN are high and the buck output voltage is 200 mV greater than the internal reference voltage, the high side FET is immediately OFF, see Section 10.4.9 for fault behavior and control. Then the internal buck output discharge FET will be turned on to discharge buck output capacitor, see Section 10.4.8 for output voltage discharge and control. An OV\_BUCK\_Event will be flagged if it is not masked. Buck will remain off and buck output will be pull-down until the fault is cleared.

### 10.4.7 Output Under-Voltage Protection

When buck output short happens, inductor current will increase until the peak reaches the cycle-by-cycle current limit. Then the high-side FET turns OFF and low-side FET turns on. Since buck output is shorted, inductor current slope is very small during low-side FET on time. The inductor current could gradually go higher and higher. To effectively prevent the inductor current running away at V<sub>OUT</sub> short condition, buck V<sub>OUT</sub> is also monitored. If over-current condition happens and buck V<sub>OUT</sub> drops 400 mV below the reference voltage, the buck regulator will be shut off immediately and an UV\_BUCK\_Event will be flagged if it is not masked, see Section 10.4.9 for fault behavior and control.

### 10.4.8 Automatic Output voltage Discharge

To speed up the discharging of buck output capacitor and ensure a safer start-up next time, the buck regulator provides automatic output voltage discharge when IC\_EN is pulled low or buck shutdown caused by any fault. Automatic output discharge when buck is forced OFF by fault needs to set register bit BUCK\_PD\_CFG1 = 0; automatic output discharge when buck is disabled by BUCK\_EN = 0 needs to set register bit BUCK\_PD\_CFG2 = 0. The output of the buck regulator is discharged through VBUCK\_SNS pin and an internal buck output discharge FET with typical 33  $\Omega$  resistance.

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## Ultra-Low Quiescent Current Buck

### 10.4.9 Event Flag and Fault Control

DA9230 has the flexibility for customers to control the behavior of buck when there is a fault condition. There are five register bits (UVLO\_FRC\_DIS, TSD\_FRC\_DIS, OV\_DIS\_BUCK, OC\_BUCK\_EVENT, SC\_DIS\_BUCK) controlling whether the buck will be disabled when the corresponding fault condition happens. In addition, users can choose whether to mask or unmask the event flag when the fault condition happens.

When there is a VDD Under-voltage condition, buck will be forced OFF if UVLO\_FRC\_DIS = 1. Buck will remain alive if UVLO\_FRC\_DIS = 0. During the VDD Under-voltage condition, the event register bit VIN\_UV\_EVENT = 1 if the corresponding mask register bit M\_VIN\_UV is set to 0 otherwise VIN\_UV\_EVENT = 0.

When there is an Over-Temperature fault inside the device, buck will be forced OFF if TSD\_FRC\_DIS = 1. If TSD\_FRC\_DIS = 0, buck will remain alive. During the over-temperature condition, the event register bit OT\_EVENT = 1.

When there is an over-voltage fault at buck output, buck will be forced OFF if OV\_DIS\_BUCK = 1. Buck will continue switching if OV\_DIS\_BUCK = 0. During the fault, OV\_BUCK\_EVENT is set to 1 if M\_OV\_BUCK\_EVENT = 0 otherwise OV\_BUCK\_EVENT = 0.

When the over-current condition in buck persists for 64  $\mu$ s and M\_OC\_BUCK\_EVENT is set to 0, OC\_BUCK\_EVENT will be set to 1. If OC\_DIS\_BUCK = 1, BUCK is forced disabled. If OC\_DIS\_BUCK = 0, buck will continue switching during the over-current condition.

When there is a buck Output under-voltage condition and M\_UV\_BUCK\_EVENT = 0, UV\_BUCK\_EVENT is set to 1. If both buck output under-voltage and over-current condition exist and SC\_DIS\_BUCK = 1, buck will be forced OFF. If SC\_DIS\_BUCK = 0, buck will continue switching without shutting down by the under-voltage protection.

DA9230 also has a fault recovery mechanism that can be customized through the 3-bits RCVRY\_NUM. This value determines the fault recovery trial number for buck and is counted down by every fault that triggers buck OFF. When RCVRY\_NUM reaches 0, recovery trial is ended and buck will remain OFF even if the buck enable signals are toggled HI. If RCVRY\_NUM is set to 0x7, there will be no count down on the recovery trial number and recovery trail will not be ended. Before RCVRY\_NUM reaches 0, buck will be recovered automatically if the fault condition disappears.

Event flags are not automatically cleared when the fault conditions disappear. They have to be cleared by changing the values in register EVENT through I<sup>2</sup>C.

## Ultra-Low Quiescent Current Buck

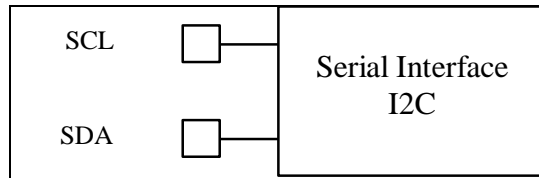
### 10.5 I<sup>2</sup>C Programming

#### 10.5.1 Interface Description

DA9230 includes an I<sup>2</sup>C compatible interface based on the following signals:

- SCL: standard 400 kHz I<sup>2</sup>C bus serial clock generated by the Host processor
- SDA: standard 400 kHz I<sup>2</sup>C bus serial address/data input output

SDA and SCL are open drain I/O terminals. The standard frequency of the I<sup>2</sup>C bus is 400 kHz in fast mode or 100 kHz in slow mode.



**Figure 43: I<sup>2</sup>C Serial Interface Pins**

The I<sup>2</sup>C bus is used to control most functions and change register values depending on the application requirements. In active battery, the I<sup>2</sup>C circuitry is powered from the battery. The interface maintains a proper operation as long as VDD\_SYS is valid.

The device is compatible with the standard I<sup>2</sup>C protocol but only operates as a slave. The transfer protocol is the same whether operating in fast or slow mode.

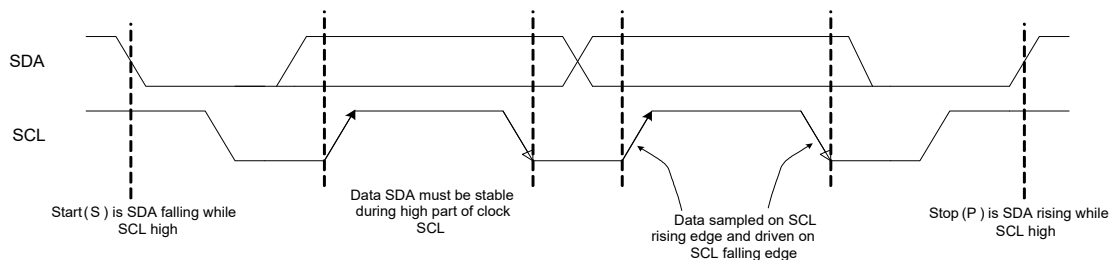
#### 10.5.2 Details of the I<sup>2</sup>C Protocol

The device supports 7-bit addressing only, the address is 0x2F. The 8-bit shifted address is 0x5E.

A timer runs during I<sup>2</sup>C transitions. If the timer expires while SDA is held low, all additional commands are ignored and the I<sup>2</sup>C state machine is reset. The timer is reset with a START condition and stopped with a STOP condition.

The I<sup>2</sup>C bus is monitored at all times for a valid SLAVE address, and an acknowledge bit is generated if the SLAVE address was true.

- A START condition is initiated by a high to low transition on the SDA line while the SCL is in the high state.
- A STOP condition is indicated by a low to high transition on the SDA line while the SCL is in the high state.
- An ACKNOWLEDGE is indicated by the receiver pulling the SDA line low during the following clock cycle.



**Figure 44: I<sup>2</sup>C Start and Stop Conditions**

## Ultra-Low Quiescent Current Buck

When the address is matching the following event sequence happens:

1. The device generates an ACKNOWLEDGE to indicate to the master that the communication link has been established
2. The master generates SCL clock cycles to transmit or receive data
3. After receiving data, an ACKNOWLEDGE is generated either by the device or the master (whichever is transmitting the data)  
A data sequence is 9-bit, consisting of 8-bit data and 1-bit ACKNOWLEDGE. It can be repeated as long as necessary.
4. The master generates a STOP condition to end the data transfer

The bus returns to IDLE-mode if during a message a new START or STOP condition occurs. Data is transmitted MSB first for both R/W operations.

### 10.6 GPO Pin Function Programing

DA9230 has a General purpose output (GPO) pin which can be programed to have multiple functions.

#### 10.6.1 Power Good Indicator

When GPO pin is configured to the VDD power good indicator, it is an open drain output and can be configured to either active high or active low. When GPO status is Hi-Z, an external pull-up is required for GPO to be high.

**Table 12: GPO as Power Good Indicator**

GPO Configuration	$V_{IN} > V_{IN\_UVLO}$	GPO Status
Active High	No	0
	Yes	Hi-Z
Active Low	No	Hi-Z
	Yes	0

#### 10.6.2 Event Indicator

GPO pin can also be configured as the event indicator in open drain output. Whenever there is an event or multiple events (VIN\_UV\_EVNT or OT\_EVENT or OV\_BUCK\_EVENT or OC\_BUCK\_EVENT or UV\_BUCK\_EVENT) happen, GPO will be pulled down Low. This can be used as an interrupt to host CPU to inform events happened. When there is no event, GPO will remain in Hi-Z status and an external pull-up is required for GPO to be high.

#### 10.6.3 Reset Pulse Generation

GPO pin can be configured to generate a reset pulse signal when buck starts. The reset signal can be used by host CPU or other device that are connected to buck output. When GPO is Low, it indicates a reset pulse period; when GPO is in Hi-Z status (An external pull-up is required for GPO to be high), it indicates a non-reset period.

There is also a timing control to negate the reset pulse signal. The GPO reset pulse width can be adjusted between 8 and 112 ms measured from written 1 to BUCK\_EN register bit.

#### 10.6.4 Always Pull-Down or Hi-Z

When GPO pin is not used, it can be configured to either always Hi-Z or pull-down to Low.



## Ultra-Low Quiescent Current Buck

### 11 Register Overview

#### 11.1 Register Map

##### 11.1.1 Buck Control

**Table 13: Event/Status/Mask and User Registers**

User Registers									
Register	Addr	7	6	5	4	3	2	1	0
EVENT	0x0000	OT_EVENT	VIN_UV_EVENT	Reserved	OC_BUCK_EVENT	OV_BUCK_EVENT	UV_BUCK_EVENT	Reserved	Reserved
STATUS	0x0002	OT_STAT	VIN_UV_STAT	Reserved	OC_BUCK_STAT	OV_BUCK_STAT	UV_BUCK_STAT	Reserved	BUCK_EN_STA T
MASK	0x0003	Reserved	M_VIN_UV	Reserved	M_OC_BUCK_EVEN T	M_OV_BUCK_EVEN T	M_UV_BUCK_EVEN T	Reserved	Reserved
GPO	0x0004	GPO_RST_CTRL<3:0>				GPO_CTRL<3:0>			
BUCK	0x0005	BUCK_EN	VOUT_RANGE_H I	Reserved	BUCK_VOUT<4:0>				
BUCK_CFG	0x0006	Reserved	Reserved	BUCK_PD_CFG 2	BUCK_PD_CFG1	Reserved	Reserved	SEL_BUCK_ILIM<1:0>	
FAULT_CTL	0x0008	SC_DIS_BUC K	OC_DIS_BUCK	OV_DIS_BUCK	TSD_FRC_DIS	UVLO_FRC_DIS	RCVRY_NUM<2:0>		
PIN_MONTOR	0x000A	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	GPO_OUT_MON

## Ultra-Low Quiescent Current Buck

### 11.1.2 System Module

**Table 14: System Reset Registers**

User Registers									
Register	Addr	7	6	5	4	3	2	1	0
SYS_RST_EVENT	0x0001	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	RESET_EVENT
SYS_SRST	0x0009	Reserved	Reserved	Reserved	Reserved	SRST<3:0>			
SYS_DEVICE_ID	0x0080	DEV_ID<7:0>							
SYS_VARIANT_ID	0x0081	MRC<3:0>				VRC<3:0>			
SYS_CONFIG_ID	0x0082	CONFIG_REV<7:0>							

## 11.2 Register Definitions

### 11.2.1 Buck Control

#### 11.2.1.1 Event/Status/Mask Registers

**Table 15: Register EVENT**

Address	Register Name	POR Value	Event flag						
0x0000	EVENT	0x00							
7	6	5	4	3	2	1	0		
OT_EVENT	VIN_UV_EVENT	Reserved	OC_BUCK_EVENT	OV_BUCK_EVENT	UV_BUCK_EVENT	Reserved	Reserved		
Field Name	Bits	Type	POR	Description					
OT_EVENT	[7]	evnt	0x0	Over Temperature fault event flag. When Over temperature condition is detected, this bit is set to 1. When I2C writes '1' to this bit, the event flag is cleared.					
VIN_UV_EVENT	[6]	evnt	0x0	Under Voltage on VDD event flag. When Under Voltage (UVLO) condition is detected, this bit is set to 1. When I2C writes '1' to this bit, the event flag is cleared.					

## Ultra-Low Quiescent Current Buck

Field Name	Bits	Type	POR	Description
OC_BUCK_EVENT	[4]	evnt	0x0	Over Current on BUCK OUT event flag. When the buck Over Current condition is detected (when BUCK_EN==1 && M_OC_BUCK==0), this bit is set to 1. When I2C writes '1' to this bit, the event flag is cleared.
OV_BUCK_EVENT	[3]	evnt	0x0	Over Voltage on BUCK OUT event flag. When the buck Over Voltage condition is detected (when BUCK_EN==1 && M_OV_BUCK==0), this bit is set to 1. When I2C writes '1' to this bit, the event flag is cleared.
UV_BUCK_EVENT	[2]	evnt	0x0	Under voltage on BUCK OUT event flag. When the under voltage condition (i.e. short circuit) is detected on the buck (when BUCK_EN==1 && M_UV_BUCK==0), this bit is set to 1. When I2C writes '1' to this bit, this event flag is cleared.

**Table 16: Register STATUS**

Address	Register Name	POR Value	Status				
0x0002	STATUS	0x00					
7	6	5	4	3	2	1	0
OT_STAT	VIN_UV_STAT	Reserved	OC_BUCK_STAT	OV_BUCK_STAT	UV_BUCK_STAT	Reserved	BUCK_EN_STAT
Field Name	Bits	Type	POR	Description			
OT_STAT	[7]	virtual	0x0	Indicate present Over Temp status.			
VIN_UV_STAT	[6]	virtual	0x0	Indicate present V <sub>IN</sub> under-voltage status.			
OC_BUCK_STAT	[4]	virtual	0x0	Indicate present BUCK VOUT over current status.			
OV_BUCK_STAT	[3]	virtual	0x0	Indicate present BUCK VOUT over voltage status.			
UV_BUCK_STAT	[2]	virtual	0x0	Indicate present BUCK VOUT under voltage status.			
BUCK_EN_STAT	[0]	virtual	0x0	Indicate present Buck Enable status. 1: Buck enabled 0: Buck disabled			

Ultra-Low Quiescent Current Buck

Table 17: Register MASK

Address	Register Name	POR Value	Mask				
0x0003	MASK	0x7C					
7	6	5	4	3	2	1	0
Reserved	M_VIN_UV	Reserved	M_OC_BUCK_EVENT	M_OV_BUCK_EVENT	M_UV_BUCK_EVENT	Reserved	Reserved
Field Name		Bits	Type	POR	Description		
M_VIN_UV		[6]	cfg OTP	0x1	Mask to set VIN_UV_EVNT. VIN_UV_STAT is updated regardless of this mask.		
M_OC_BUCK_EVENT		[4]	cfg OTP	0x1	Masks to set OC_BUCK_EVENT. OC_BUCK_STAT is updated regardless of this mask.		
M_OV_BUCK_EVENT		[3]	cfg OTP	0x1	Masks to set OV_BUCK_EVENT. OV_BUCK_STAT is updated regardless of this mask.		
M_UV_BUCK_EVENT		[2]	cfg OTP	0x1	Masks to set UV_BUCK_EVENT. UV_BUCK_STAT is updated regardless of this mask.		

11.2.1.2 User Registers

Table 18: Register GPO

Address	Register Name	POR Value	GPO control				
0x0004	GPO	0x00					
7	6	5	4	3	2	1	0
GPO_RST_CTRL<3:0>				GPO_CTRL<3:0>			
Field Name		Bits	Type	POR	Description		
GPO_RST_CTRL		[7:4]	cfg OTP	0x0	Reset pulse signal nagate timing control		
					Value	Description	
					0x0	8ms after BUCK_EN = 1, GPO reset pulse is negated.	

Ultra-Low Quiescent Current Buck

Field Name	Bits	Type	POR	Description														
				<table border="1"> <tr> <td>0x1</td> <td>16ms after BUCK_EN = 1, GPO reset pulse is negated.</td> </tr> <tr> <td>0x2</td> <td>32ms after BUCK_EN = 1, GPO reset pulse is negated.</td> </tr> <tr> <td>0x3</td> <td>48ms after BUCK_EN = 1, GPO reset pulse is negated.</td> </tr> <tr> <td>0x4</td> <td>64ms after BUCK_EN = 1, GPO reset pulse is negated.</td> </tr> <tr> <td>0x5</td> <td>80ms after BUCK_EN = 1, GPO reset pulse is negated.</td> </tr> <tr> <td>0x6</td> <td>96ms after BUCK_EN = 1, GPO reset pulse is negated.</td> </tr> <tr> <td>0x7</td> <td>112ms after BUCK_EN = 1, GPO reset pulse is negated.</td> </tr> </table>	0x1	16ms after BUCK_EN = 1, GPO reset pulse is negated.	0x2	32ms after BUCK_EN = 1, GPO reset pulse is negated.	0x3	48ms after BUCK_EN = 1, GPO reset pulse is negated.	0x4	64ms after BUCK_EN = 1, GPO reset pulse is negated.	0x5	80ms after BUCK_EN = 1, GPO reset pulse is negated.	0x6	96ms after BUCK_EN = 1, GPO reset pulse is negated.	0x7	112ms after BUCK_EN = 1, GPO reset pulse is negated.
0x1	16ms after BUCK_EN = 1, GPO reset pulse is negated.																	
0x2	32ms after BUCK_EN = 1, GPO reset pulse is negated.																	
0x3	48ms after BUCK_EN = 1, GPO reset pulse is negated.																	
0x4	64ms after BUCK_EN = 1, GPO reset pulse is negated.																	
0x5	80ms after BUCK_EN = 1, GPO reset pulse is negated.																	
0x6	96ms after BUCK_EN = 1, GPO reset pulse is negated.																	
0x7	112ms after BUCK_EN = 1, GPO reset pulse is negated.																	
GPO_CTRL	[3:0]	cfg OTP	0x0	<p>GPO Control</p> <table border="1"> <thead> <tr> <th>Value</th> <th>Description</th> </tr> </thead> <tbody> <tr> <td>0x1</td> <td>Reset Pulse generation output</td> </tr> <tr> <td>0x2</td> <td>PowerGood indicator, Active Low</td> </tr> <tr> <td>0x3</td> <td>PowerGood indicator, Active High</td> </tr> <tr> <td>0x4</td> <td>Event indicator</td> </tr> <tr> <td>0x8</td> <td>Force GPO output low</td> </tr> <tr> <td>0x9</td> <td>Force GPO output hi-z</td> </tr> </tbody> </table>	Value	Description	0x1	Reset Pulse generation output	0x2	PowerGood indicator, Active Low	0x3	PowerGood indicator, Active High	0x4	Event indicator	0x8	Force GPO output low	0x9	Force GPO output hi-z
Value	Description																	
0x1	Reset Pulse generation output																	
0x2	PowerGood indicator, Active Low																	
0x3	PowerGood indicator, Active High																	
0x4	Event indicator																	
0x8	Force GPO output low																	
0x9	Force GPO output hi-z																	

Table 19: Register BUCK

Address	Register Name	POR Value	Buck enable & vout control							
0x0005	BUCK	0x58								
7	6	5	4	3	2	1	0			
BUCK_EN	VOUT_RANGE_HI	Reserved	BUCK_VOUT<4:0>							

## Ultra-Low Quiescent Current Buck

Field Name	Bits	Type	POR	Description	
BUCK_EN	[7]	cfg OTP	0x0	BUCK enable	
VOUT_RANGE_HI	[6]	cfg OTP	0x1	Range selection for buck. This can only be changed while BUCK_EN = 0	
				<b>Value</b>	<b>Description</b>
				0x0	0.60 V <= VBUCK <= 1.30 V
				0x1	1.30 V <= VBUCK <= 1.90 V
BUCK_VOUT	[4:0]	datablk OTP	0x18	Buck output voltage	
				<b>Value</b>	<b>Description</b>
				0x00	0.60 V
				0x01	0.65 V
				0x02	0.70 V
				0x03	0.75 V
				0x04	0.80 V
				0x05	0.85 V
				0x06	0.90 V
				0x07	0.95 V
				0x08	1.00 V
				0x09	1.05 V
				0x0A	1.10 V
0x0B	1.15 V				
0x0C	1.20 V				
0x0D	1.25 V				
0x0E	1.30 V				

Ultra-Low Quiescent Current Buck

Field Name	Bits	Type	POR	Description
				0x0F 1.35 V
				0x10 1.40 V
				0x11 1.45 V
				0x12 1.50 V
				0x13 1.55 V
				0x14 1.60 V
				0x15 1.65 V
				0x16 1.70 V
				0x17 1.75 V
				0x18 1.80 V
				0x19 1.85 V
				0x1A 1.90 V
				0x1B 1.90 V
				0x1C 1.90 V
				0x1D 1.90 V
				0x1E 1.90 V
				0x1F 1.90 V

Table 20: Register BUCK\_CFG

Address	Register Name	POR Value	Buck config				
0x0006	BUCK_CFG	0x00					
7	6	5	4	3	2	1	0
Reserved	Reserved	BUCK_PD_CFG2	BUCK_PD_CFG1	Reserved	Reserved	SEL_BUCK_ILIM<1:0>	

## Ultra-Low Quiescent Current Buck

Field Name	Bits	Type	POR	Description	
BUCK_PD_CFG2	[5]	cfg OTP	0x0	0: If BUCK_EN = 0, BUCK_PD_EN = 1 1: If BUCK_EN = 0, BUCK_PD_EN = 0	
BUCK_PD_CFG1	[4]	cfg OTP	0x0	0: When BUCK is forced off by faults, BUCK_PD_EN = 1 1: When BUCK is forced off by faults, BUCK_PD_EN = 0	
SEL_BUCK_ILIM	[1:0]	cfg OTP	0x0	Buck peak current limit setting	
				<b>Value</b>	<b>Description</b>
				0x0	Default current limit
				0x1	Default +50mA
				0x2	Default +100mA
0x3	Default +150mA				

**Table 21: Register FAUL\_CTL**

Address	Register Name	POR Value	Fault & Recovery control				
0x0008	FAUL_CTL	0x1F					
<b>7</b>	<b>6</b>	<b>5</b>	<b>4</b>	<b>3</b>	<b>2</b>	<b>1</b>	<b>0</b>
SC_DIS_BUCK	OC_DIS_BUCK	OV_DIS_BUCK	TSD_FRC_DIS	UVLO_FRC_DIS	RCVRY_NUM<2:0>		
Field Name	Bits	Type	POR	Description			
SC_DIS_BUCK	[7]	cfg OTP	0x0	1: Force disable BUCK during SHORT CIRCUIT condition oc_buck=1 & uv_buck=1			
OC_DIS_BUCK	[6]	cfg OTP	0x0	1: Force disable BUCK during oc_buck=1 for over 64 cycles			
OV_DIS_BUCK	[5]	cfg OTP	0x0	1: Force disable BUCK during ov_buck=1			
TSD_FRC_DIS	[4]	cfg OTP	0x1	1: Force disable BUCK during Over Temp			
UVLO_FRC_DIS	[3]	cfg OTP	0x1	1: Force disable BUCK during UVLO			
RCVRY_NUM	[2:0]	data OTP	0x7	BUCK recovery trial fault number. This is counted down by every fault forcing BUCK off. If RCVRY_NUM becomes 0, Recovery trial is ended. If RCVRY_NUM is set 0x7, this is not counted down and recovery trail is not ended.			



## Ultra-Low Quiescent Current Buck

**Table 22: Register PIN\_MONITOR**

Address	Register Name	POR Value	PIN MONITOR				
0x000A	PIN_MONTOR	0x00					
7	6	5	4	3	2	1	0
Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	GPO_OUT_MON
Field Name	Bits	Type	POR	Description			
GPO_OUT_MON	[0]	virtual	0x0	Indicate current GPO output			

### 11.2.2 System Module

#### 11.2.2.1 System Reset Registers

**Table 23: Register SYS\_RST\_EVENT**

Address	Register Name	POR Value	Reset Event flag				
0x0001	SYS_RST_EVENT	0x01					
7	6	5	4	3	2	1	0
Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	Reserved	RESET_EVENT
Field Name	Bits	Type	POR	Description			
RESET_EVENT	[0]	evnt	0x1	RESET event flag. After Reset, this bit is set. When I2C write '1' to this bit, this event flag is cleared.			

**Table 24: Register SYS\_SRST**

Address	Register Name	POR Value	Soft Reset				
0x0009	SYS_SRST	0x00					
7	6	5	4	3	2	1	0
Reserved	Reserved	Reserved	Reserved	SRST<3:0>			

## Ultra-Low Quiescent Current Buck

Field Name	Bits	Type	POR	Description
SRST	[3:0]	cfg	0x0	Initiate Soft Reset by writing 0x5.

### 11.2.2.2 System ID Registers

**Table 25: Register SYS\_DEVICE\_ID**

Address	Register Name	POR Value	DEVICE_ID				
0x0080	SYS_DEVICE_ID	0x00					
7	6	5	4	3	2	1	0
DEV_ID<7:0>							
Field Name	Bits	Type	POR	Description			
DEV_ID	[7:0]	virtual	0x0	Device ID; hard-coded or metal-programmed			

**Table 26: Register SYS\_VARIANT\_ID**

Address	Register Name	POR Value	VARIANT_ID				
0x0081	SYS_VARIANT_ID	0x00					
7	6	5	4	3	2	1	0
MRC<3:0>				VRC<3:0>			
Field Name	Bits	Type	POR	Description			
MRC	[7:4]	virtual	0x0	Mask Revision Code; mask design changes increment reset value.			
VRC	[3:0]	trim OTP	0x0	Chip Variant Code; e.g. package variants.			

Ultra-Low Quiescent Current Buck

Table 27: Register SYS\_CONFIG\_ID

Address	Register Name	POR Value	CONFIG_ID				
0x0082	SYS_CONFIG_ID	0x00					
7	6	5	4	3	2	1	0
CONFIG_REV<7:0>							
Field Name	Bits	Type	POR	Description			
CONFIG_REV	[7:0]	trim OTP	0x0	OTP settings revision			

Ultra-Low Quiescent Current Buck

## 12 Package Information

### 12.1 Package Outlines

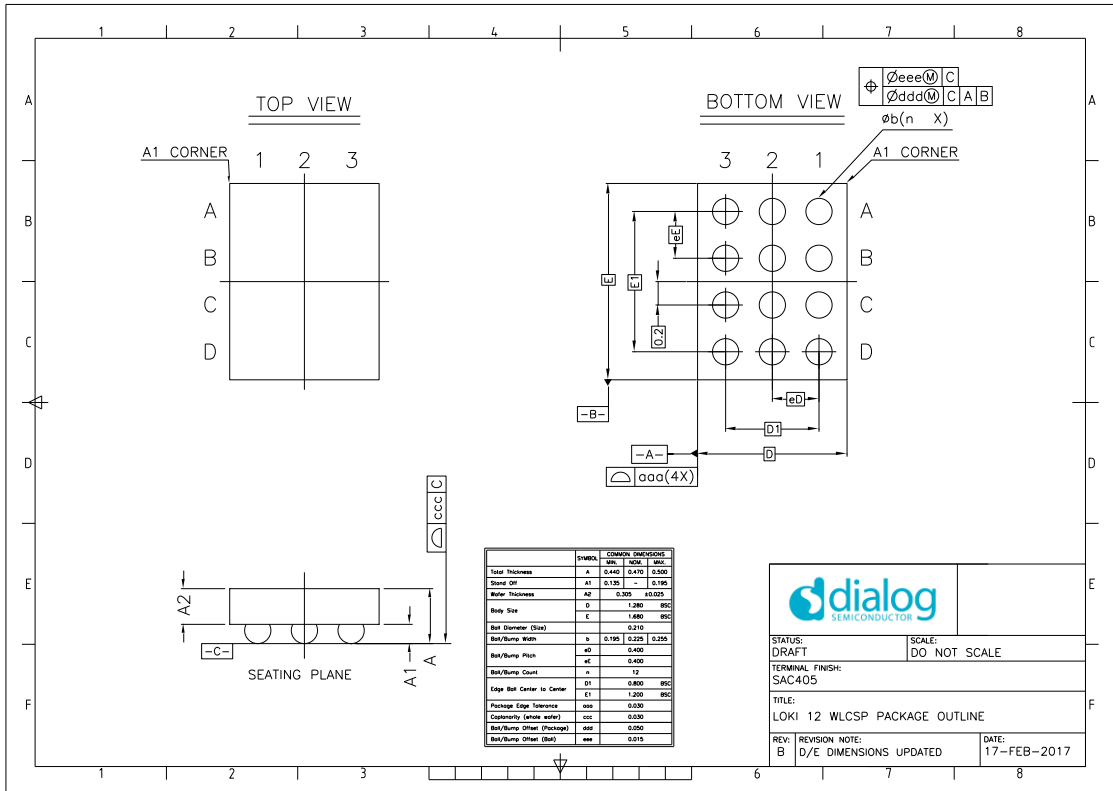


Figure 45: Package Outline Drawing

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## Ultra-Low Quiescent Current Buck

### 12.2 Moisture Sensitivity Level

The Moisture Sensitivity Level (MSL) is an indicator for the maximum allowable time period (floor lifetime) in which a moisture sensitive plastic device, once removed from the dry bag, can be exposed to an environment with a maximum temperature of 30 °C and a maximum relative humidity of 60% RH before the solder reflow process. The MSL classification is defined in [Table 28](#).

The device package is qualified for MSL 1.

**Table 28: MSL Classification**

MSL level	Floor Lifetime
MSL 1	unlimited at 30 °C/85% RH

### 12.3 Soldering Information

Refer to the JEDEC standard J-STD-020 for relevant soldering information. This document can be downloaded from <http://www.jedec.org>.

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**Ultra-Low Quiescent Current Buck**

### 13 Ordering Information

The ordering number consists of the part number followed by a suffix indicating the packing method. For details and availability or other custom OTP parts, please consult Dialog Semiconductor's [customer portal](#) or your local sales representative.

**Table 29: Ordering Information**

Part number	Package	Size (mm)	Shipment Form	Pack Quantity
DA9230 -xxxx	WLCSP-12	1.25 x 1.65	T&R	4500

**Table 30: OTP List**

Order code	Description	Buck V <sub>OUT</sub>
DA9230-07VZ2	OTP with buck voltage preconfigured	0.6 V
DA9230-08VZ2	OTP with buck voltage preconfigured	0.8 V
DA9230-09VZ2	OTP with buck voltage preconfigured	1.2 V
DA9230-0AVZ2	OTP with buck voltage preconfigured	1.8 V
DA9230-61VZ2	OTP with buck voltage preconfigured	1.9 V
DA9230-62VZ2	OTP with buck voltage preconfigured	1.1 V

## Ultra-Low Quiescent Current Buck

### Status Definitions

Revision	Datasheet Status	Product Status	Definition
1.<n>	Target	Development	This datasheet contains the design specifications for product development. Specifications may be changed in any manner without notice.
2.<n>	Preliminary	Qualification	This datasheet contains the specifications and preliminary characterization data for products in pre-production. Specifications may be changed at any time without notice in order to improve the design.
3.<n>	Final	Production	This datasheet contains the final specifications for products in volume production. The specifications may be changed at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via Customer Product Notifications.
4.<n>	Obsolete	Archived	This datasheet contains the specifications for discontinued products. The information is provided for reference only.

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(Rev.1.0 Mar 2020)

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